

**FIG. 1**

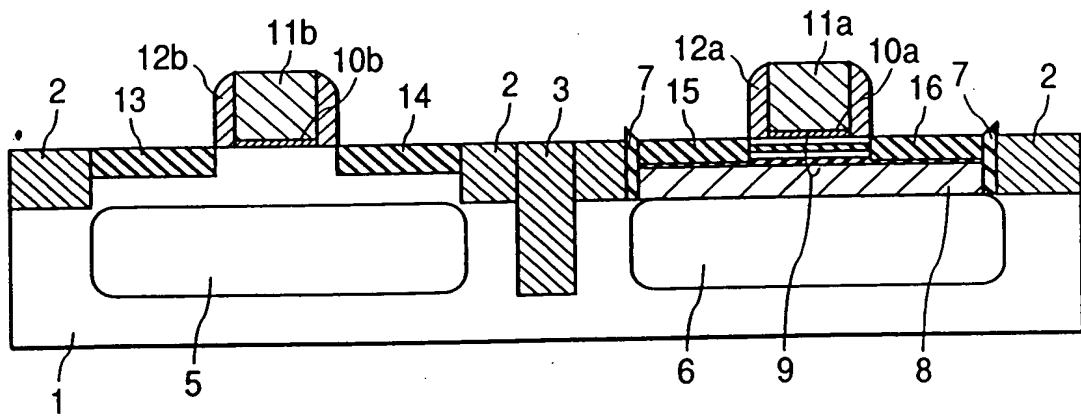


FIG. 2(a)

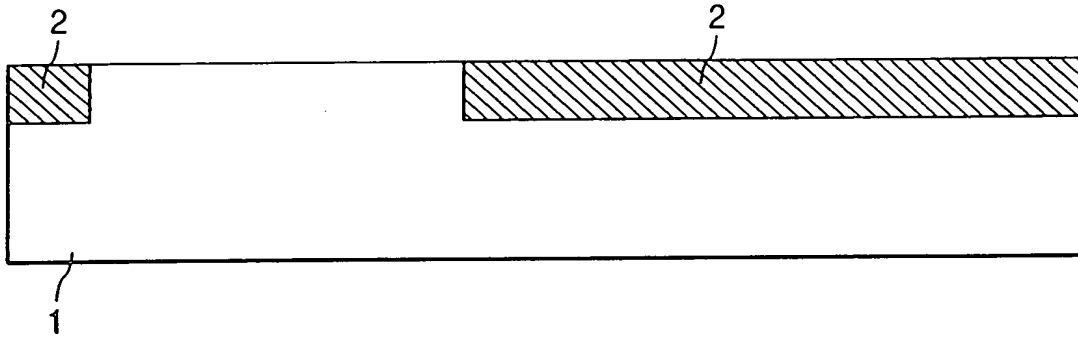


FIG. 2(b)

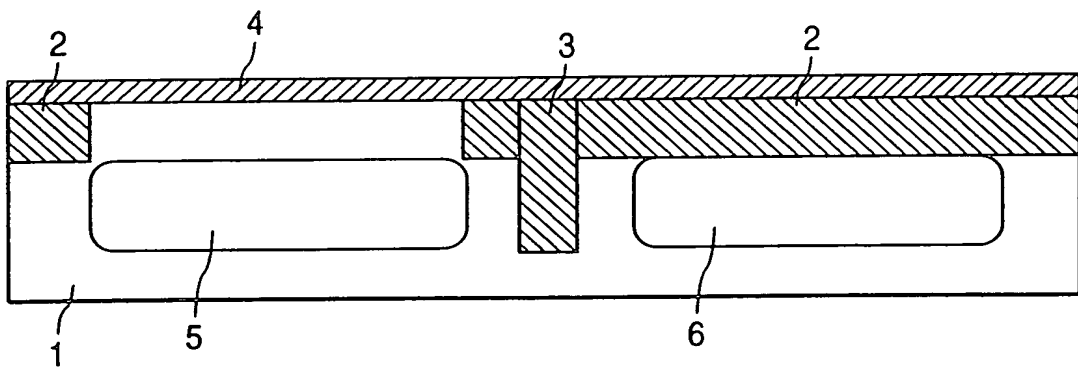
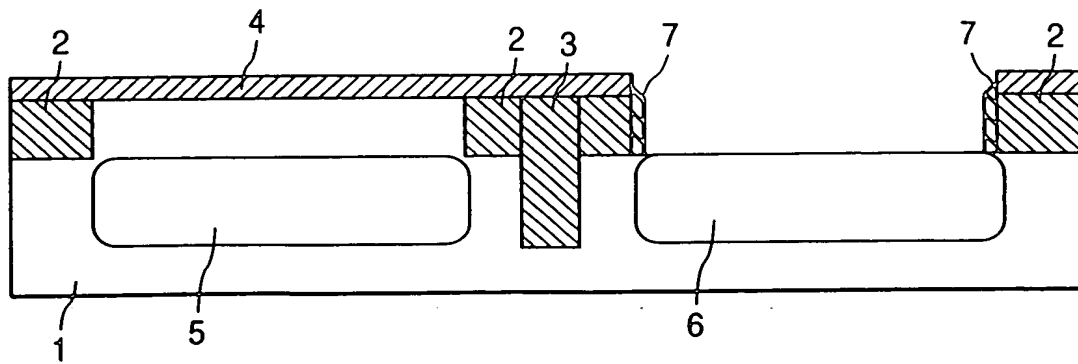
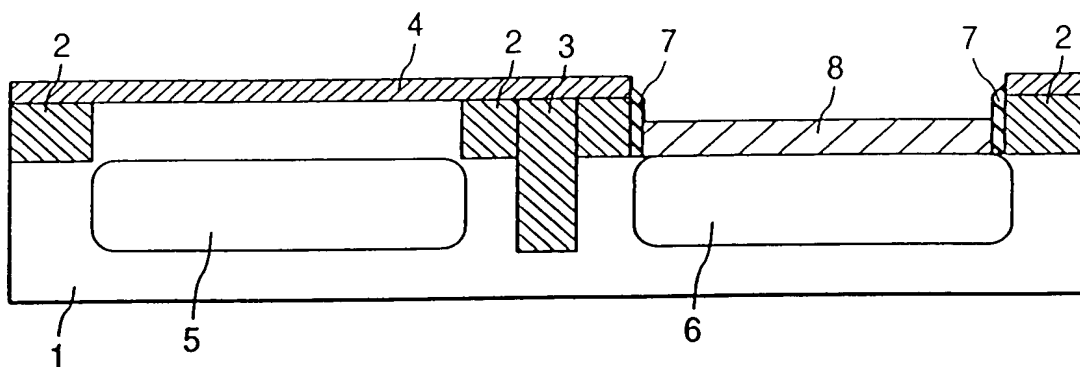


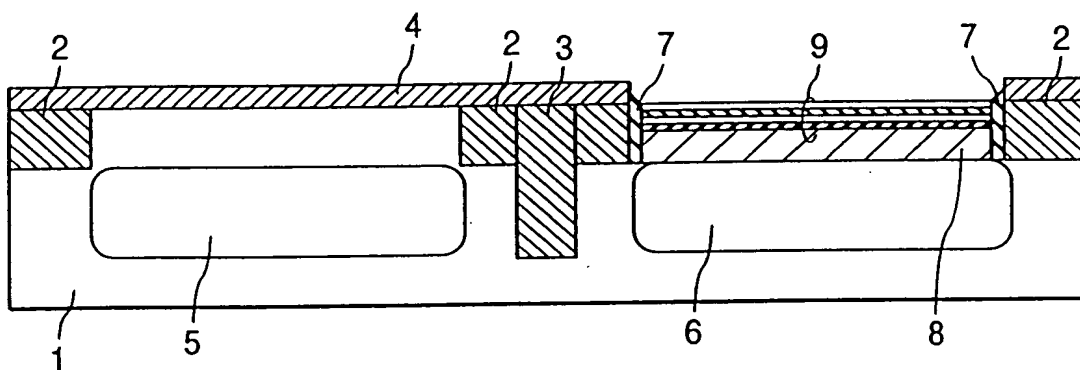
FIG. 2(c)



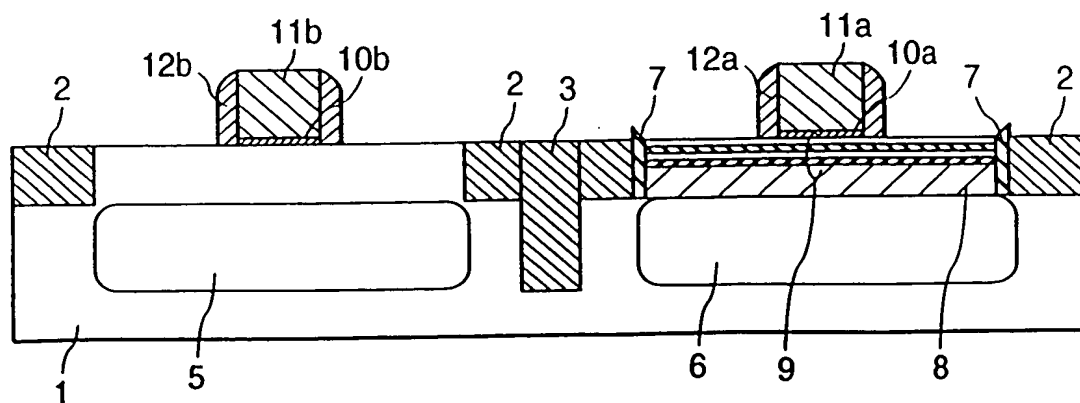
*FIG. 3(a)*



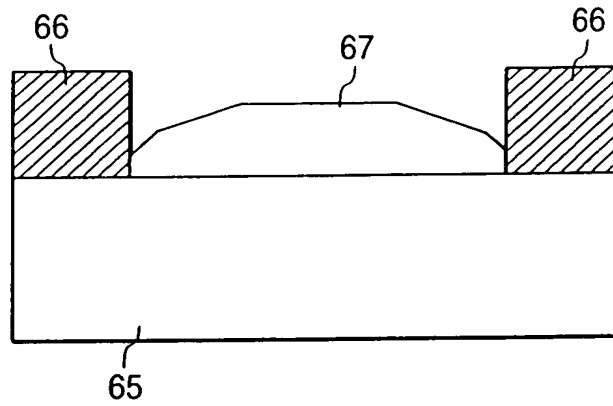
*FIG. 3(b)*



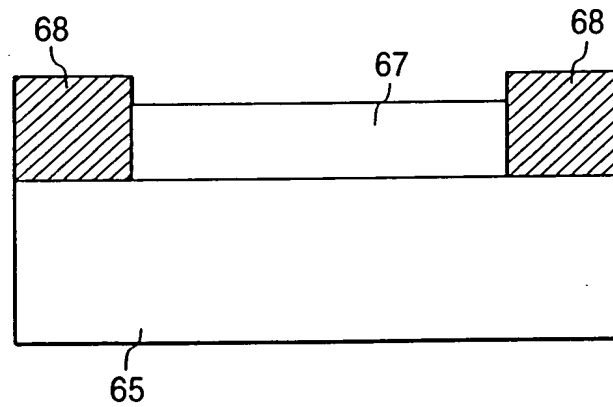
*FIG. 3(c)*



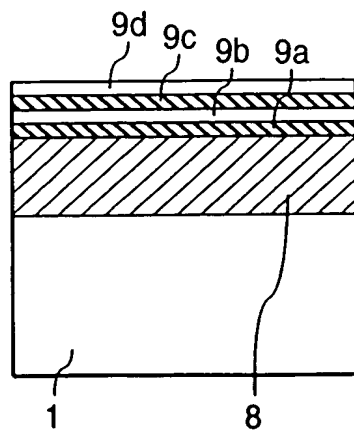
*FIG. 4(a)*



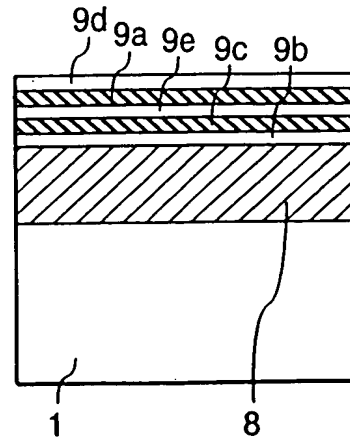
*FIG. 4(b)*



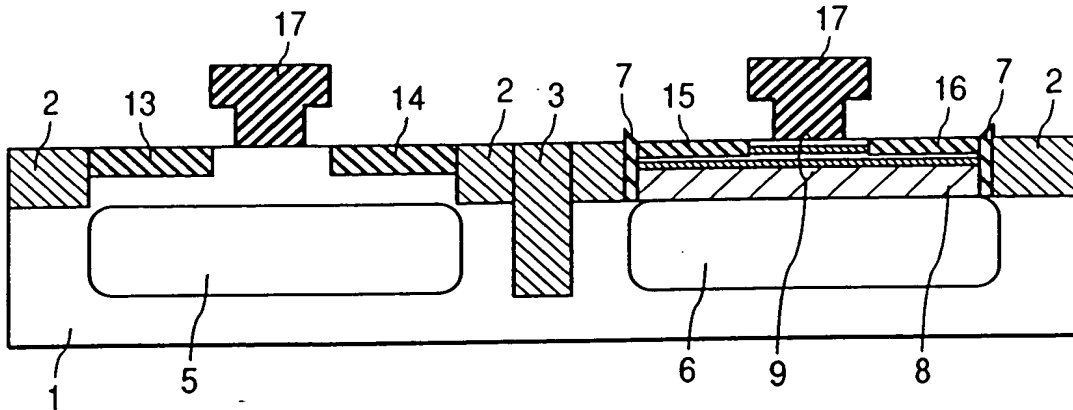
*FIG. 5*



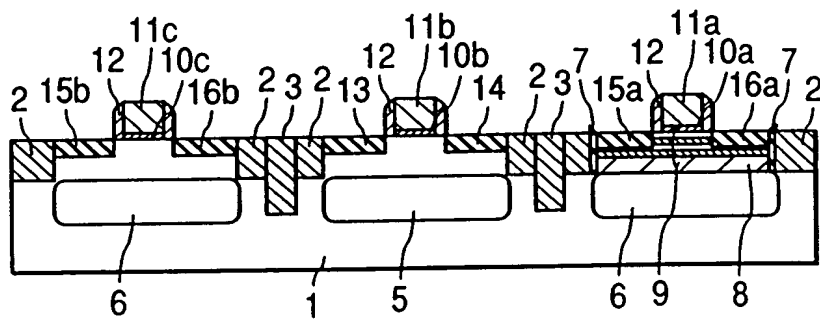
*FIG. 6*



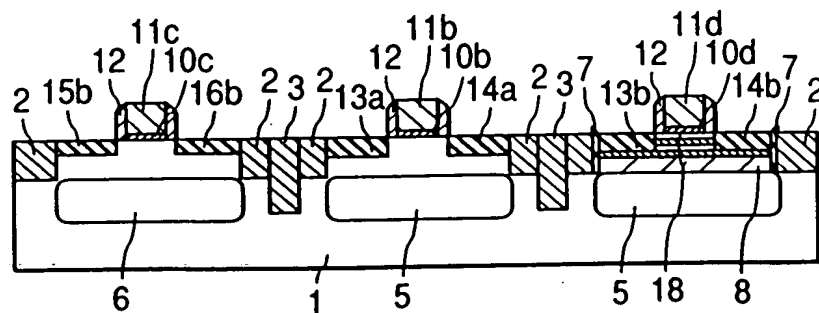
**FIG. 7**



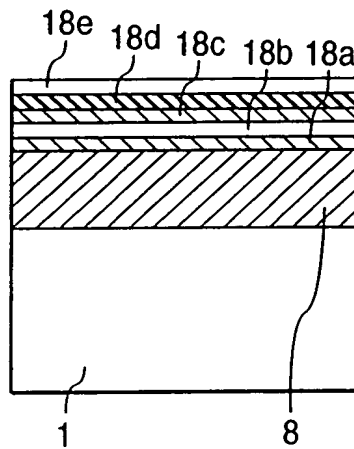
**FIG. 8**



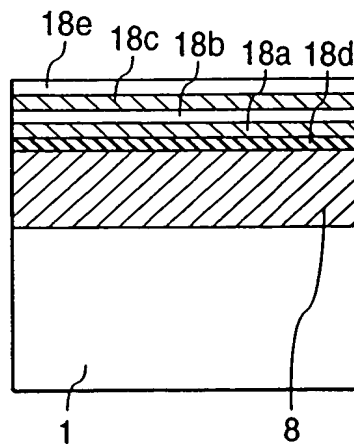
**FIG. 9**



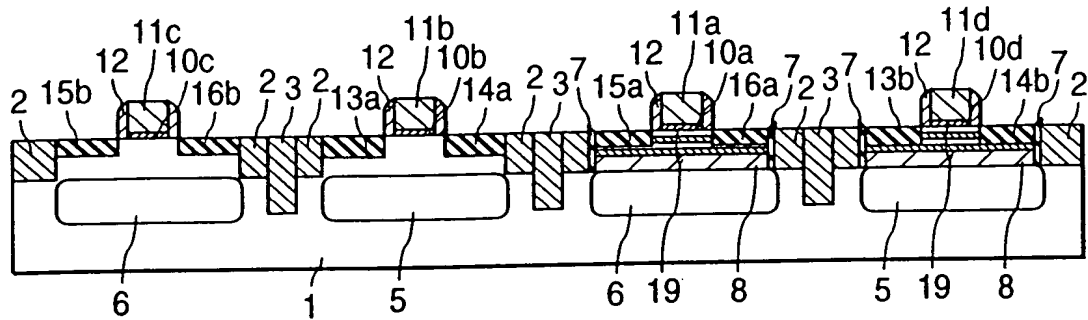
*FIG. 10*



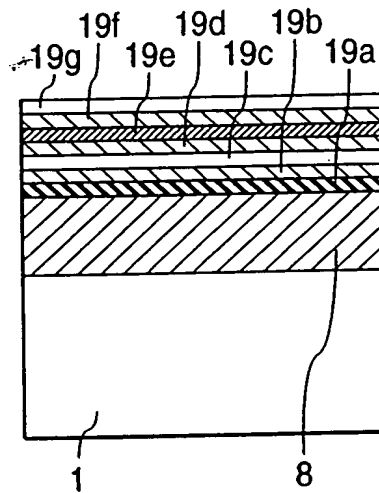
*FIG. 11*



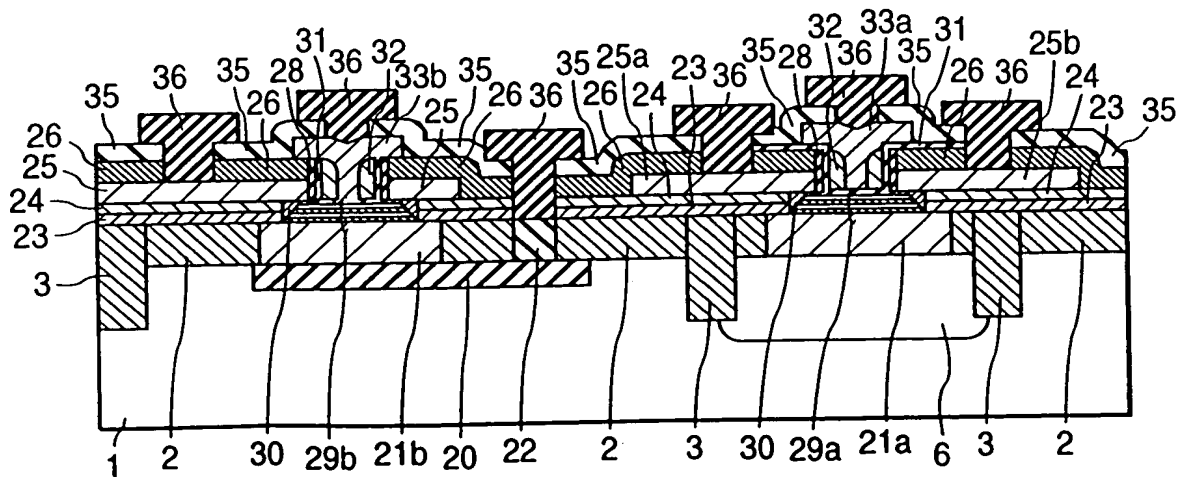
**FIG. 12**



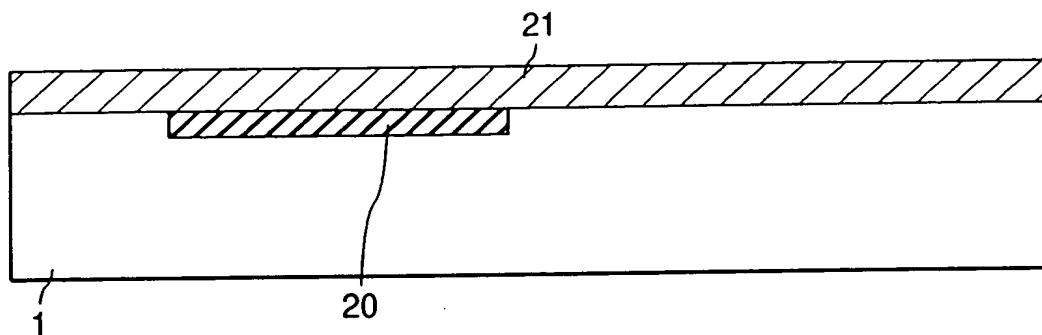
**FIG. 13**



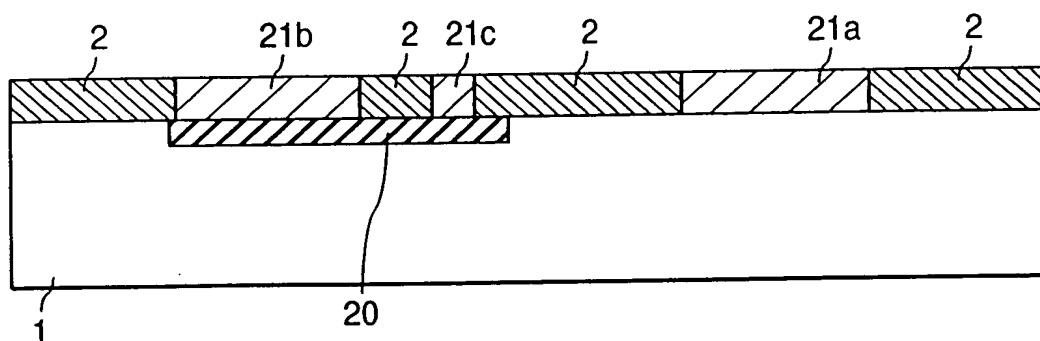
**FIG. 14**



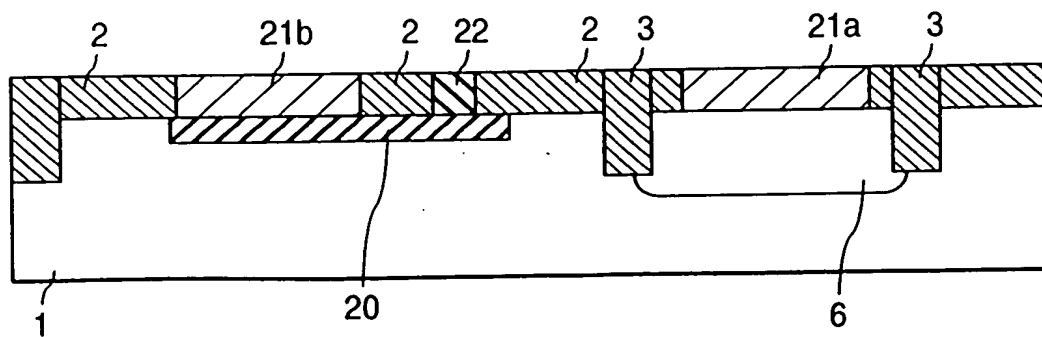
*FIG. 15(a)*



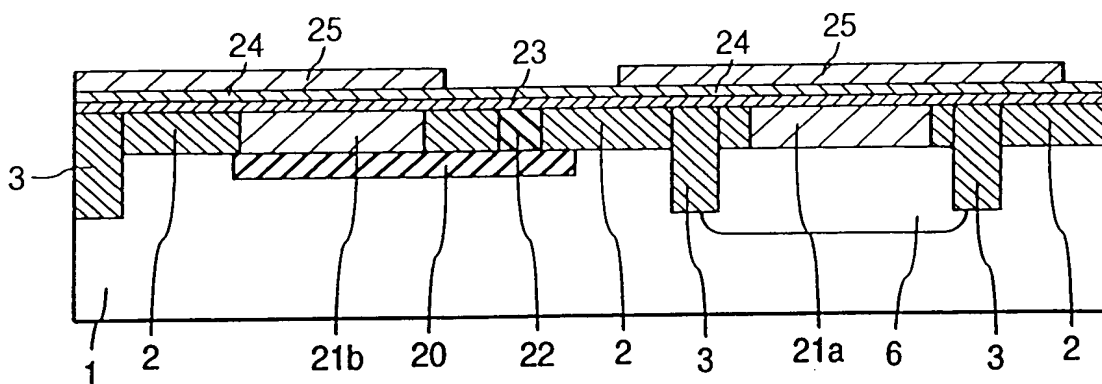
*FIG. 15(b)*



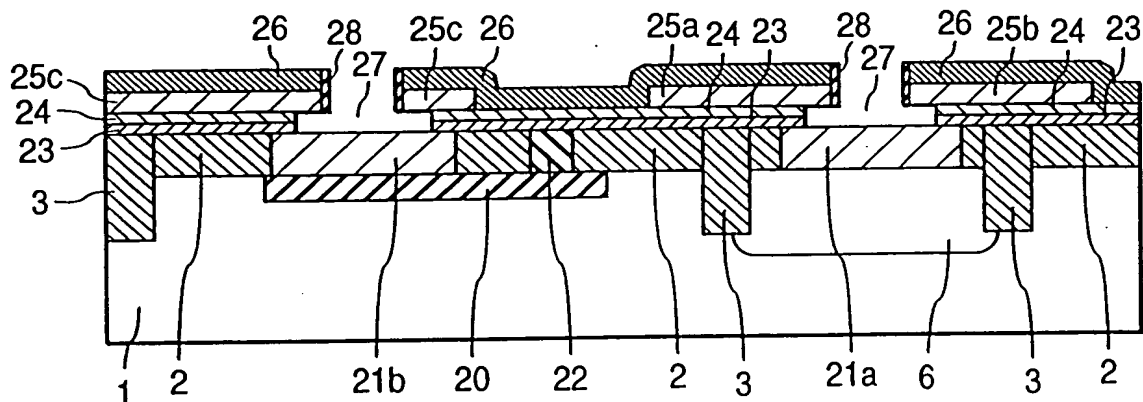
*FIG. 15(c)*



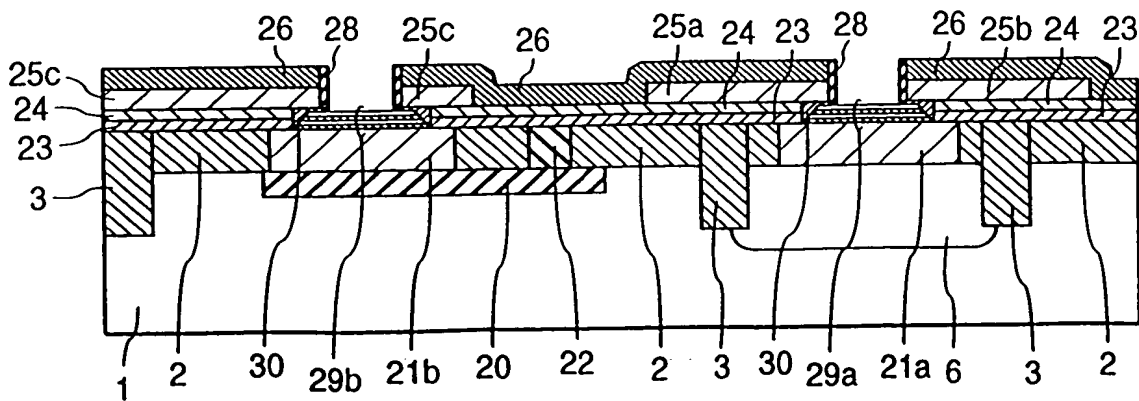
*FIG. 16(a)*



*FIG. 16(b)*



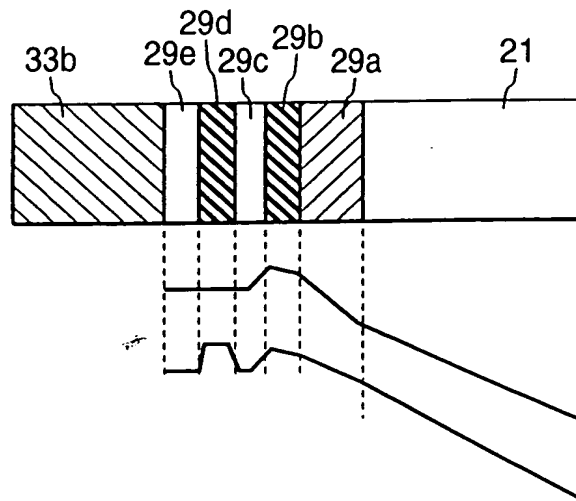
*FIG. 16(c)*



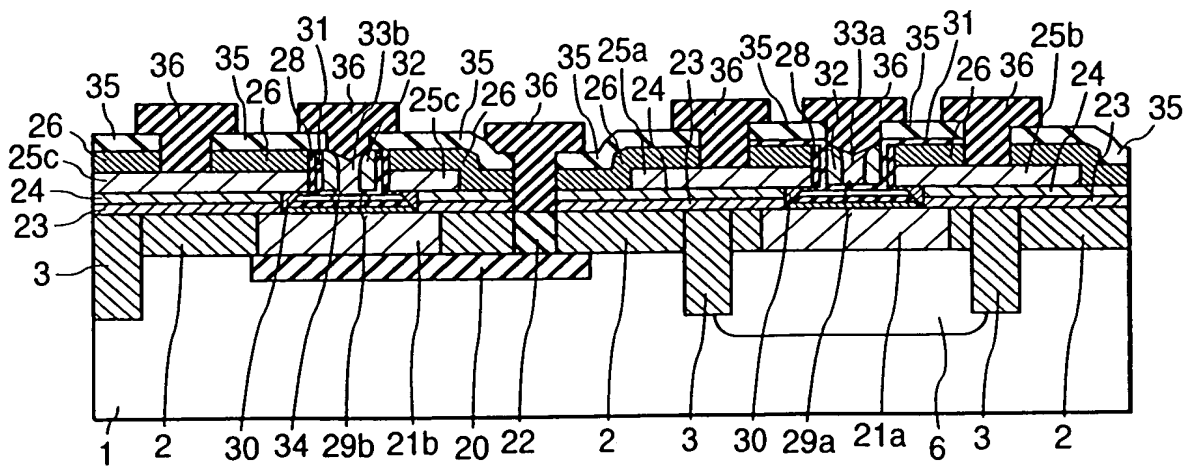
This cross-sectional diagram illustrates a multi-layered semiconductor device. The base layer is labeled 1. Above it are several regions: 2, 30, 29b, 21b, 20, 22, 2, 3, 30, 29a, 21a, 6, 3, and 2. A central horizontal layer is labeled 23. Above this layer are various structures: 25c, 24, 26, 28, 31, 32, 25a, 24, 23, 28, 32, 31, 26, 25b, 24, and 23. The topmost layer is labeled 25c.

[illegible]

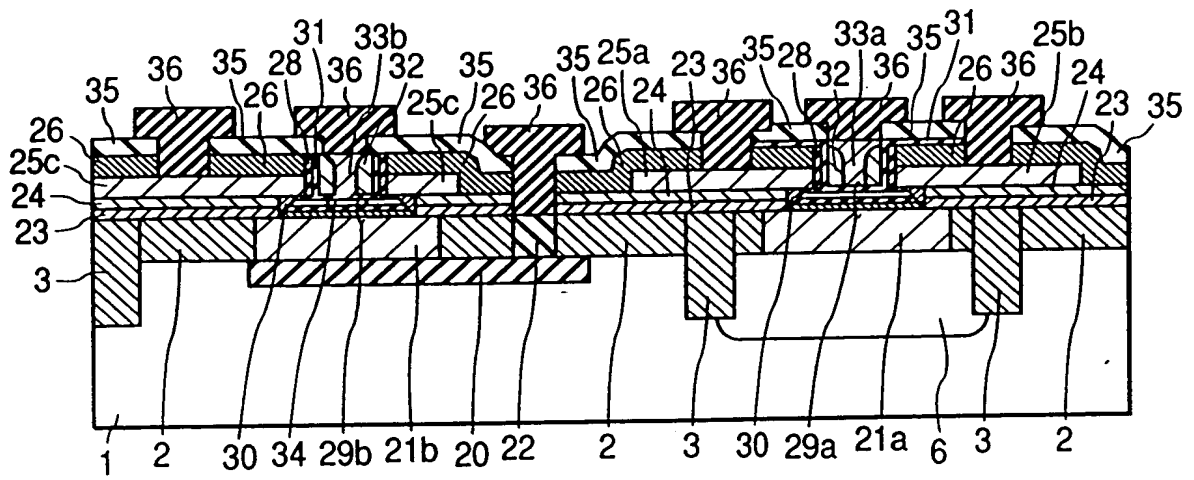
**FIG. 18**



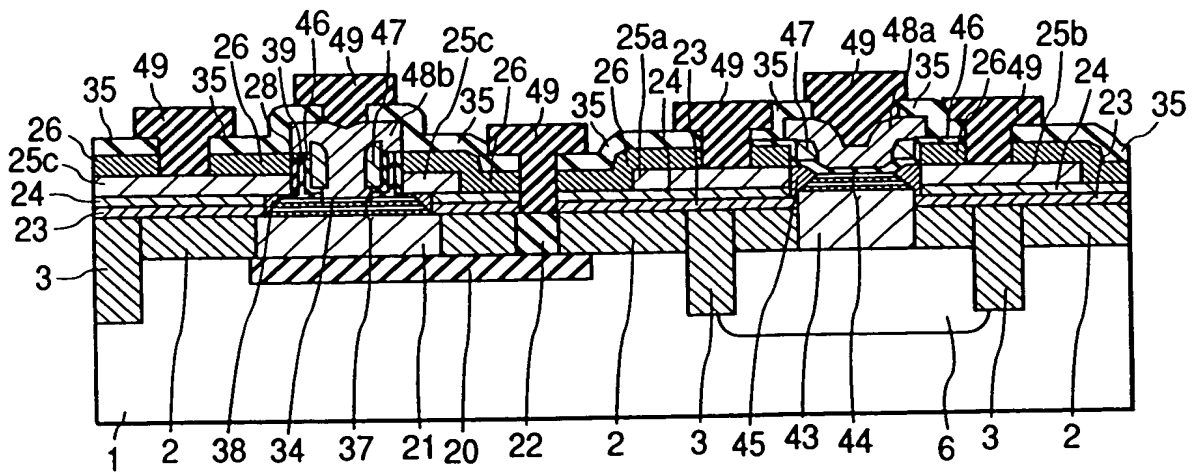
**FIG. 19**



**FIG. 20**



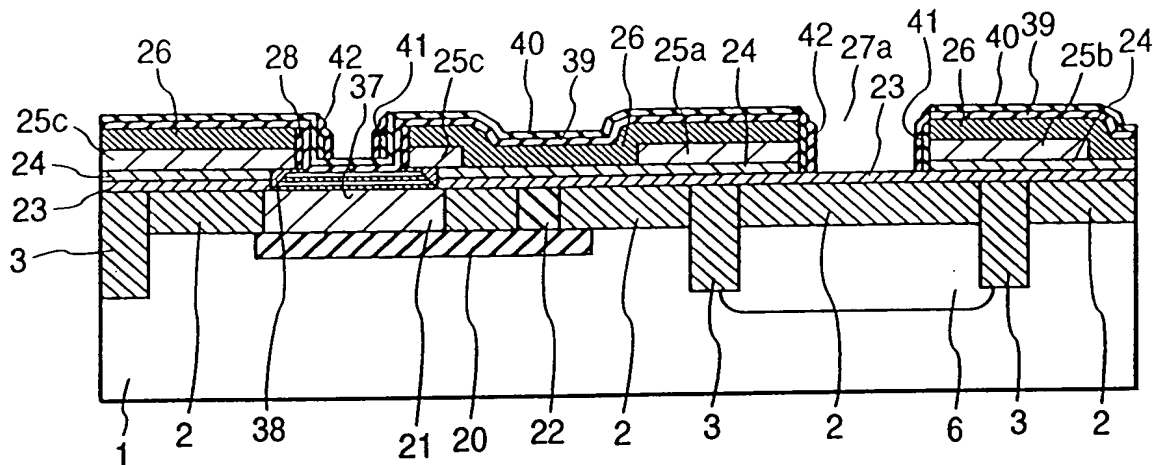
**FIG. 21**



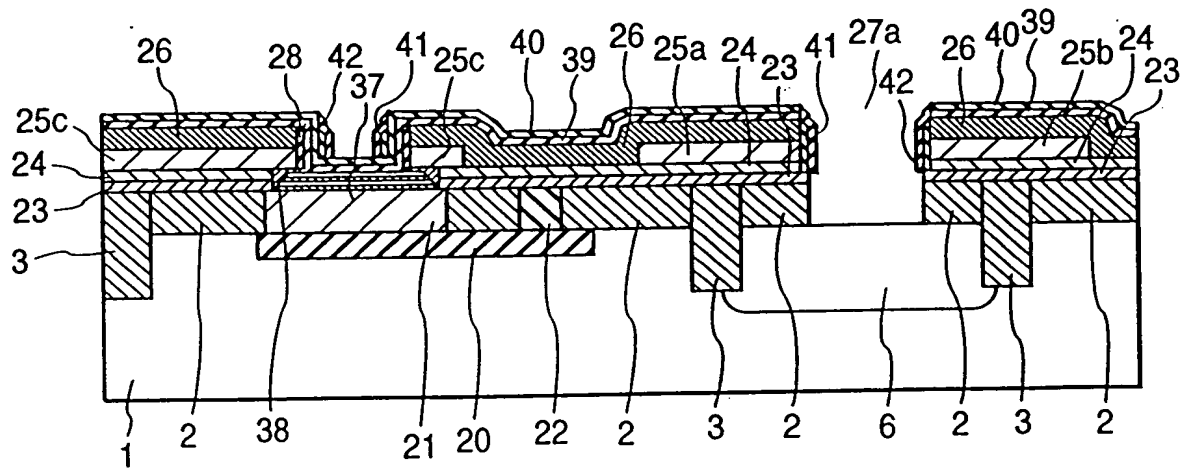
A cross-sectional view of a multi-layered structure. The structure consists of several layers and components. At the bottom is a thick, solid layer labeled 1. Above this layer is a series of alternating layers and components. A layer labeled 2 is shown in several segments. A component labeled 3 is shown in several segments, some of which are connected by a horizontal line labeled 6. A component labeled 20 is shown in a central segment. A component labeled 21 is shown in a segment to the left of 20. A component labeled 22 is shown in a segment to the right of 20. The layers and components are shown in different patterns of hatching to distinguish them.

[illegible]

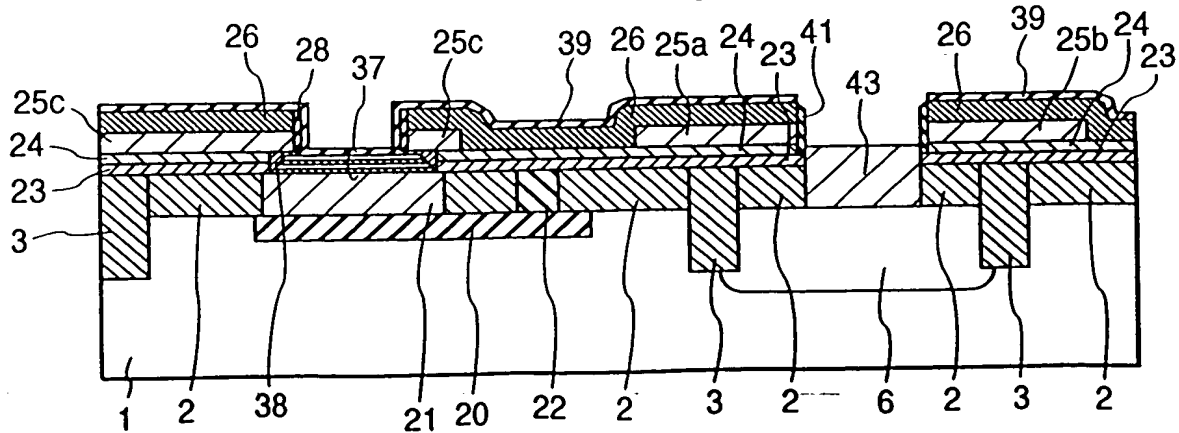
*FIG. 23(a)*



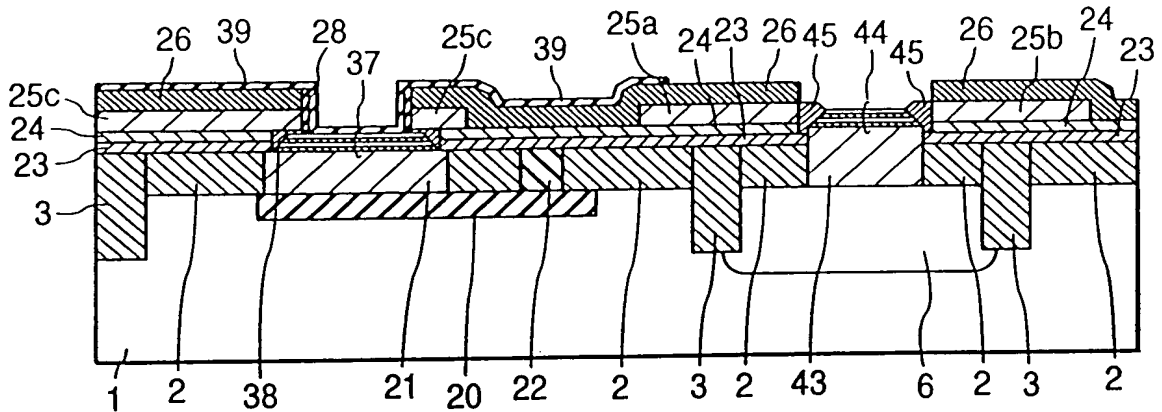
*FIG. 23(b)*



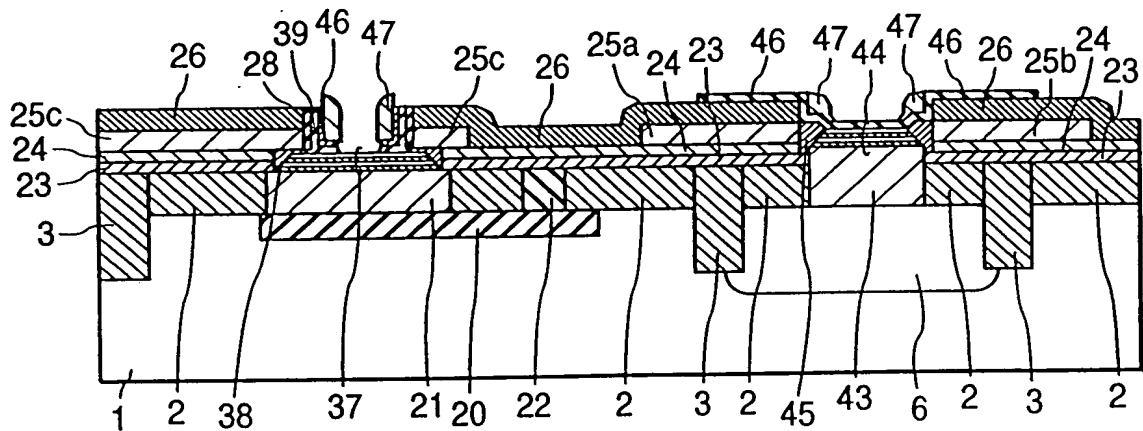
*FIG. 23(c)*



*FIG. 24(a)*



*FIG. 24(b)*



*FIG. 24(c)*

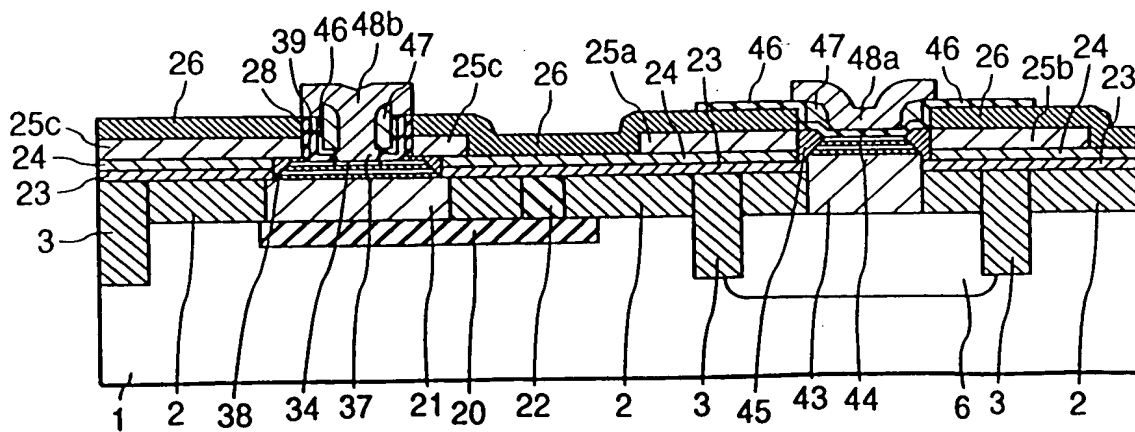


FIG. 25

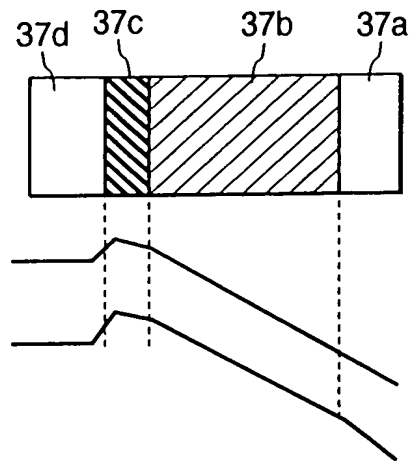


FIG. 26(a)

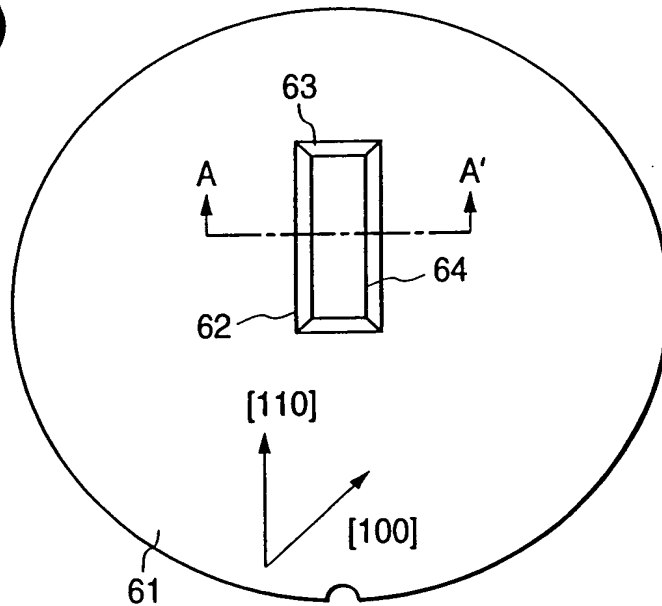
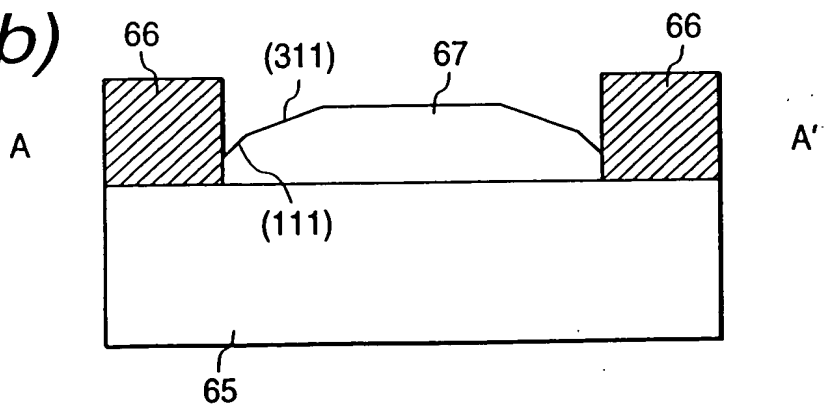
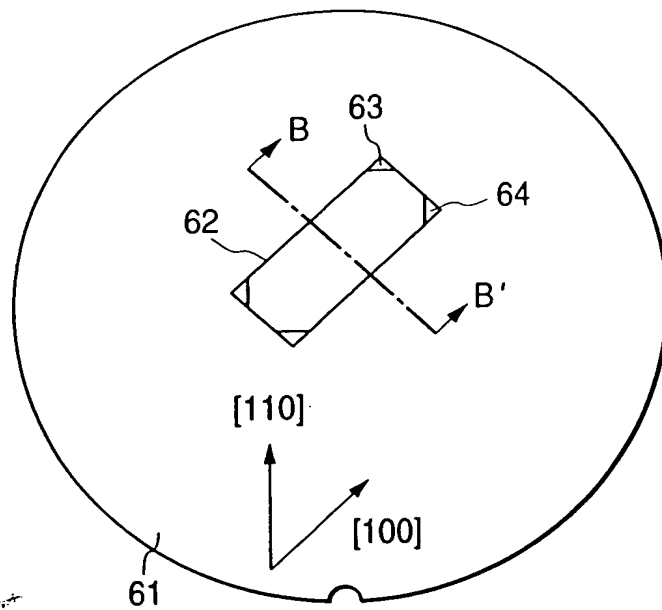


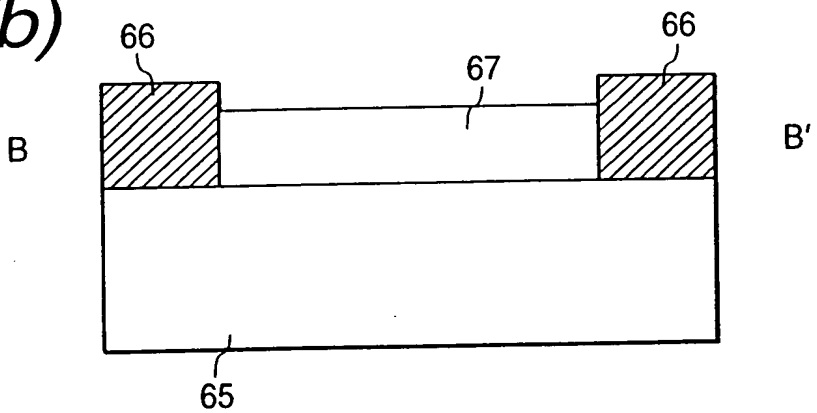
FIG. 26(b)



**FIG. 27(a)**



**FIG. 27(b)**



**FIG. 28**

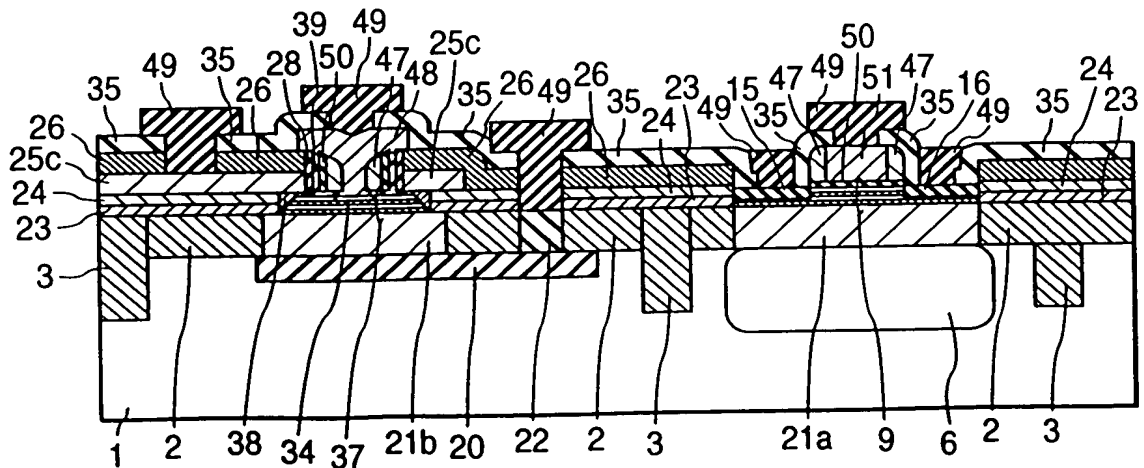


FIG. 29(a)

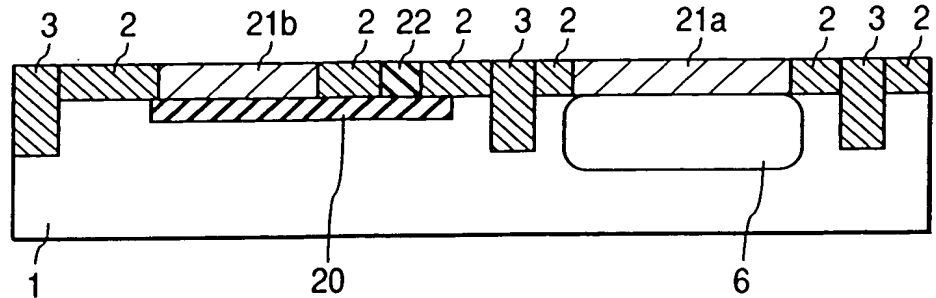


FIG. 29(b)

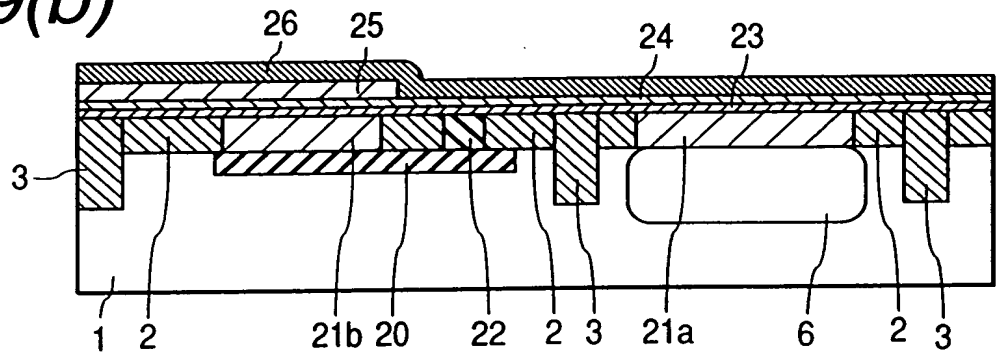


FIG. 29(c)

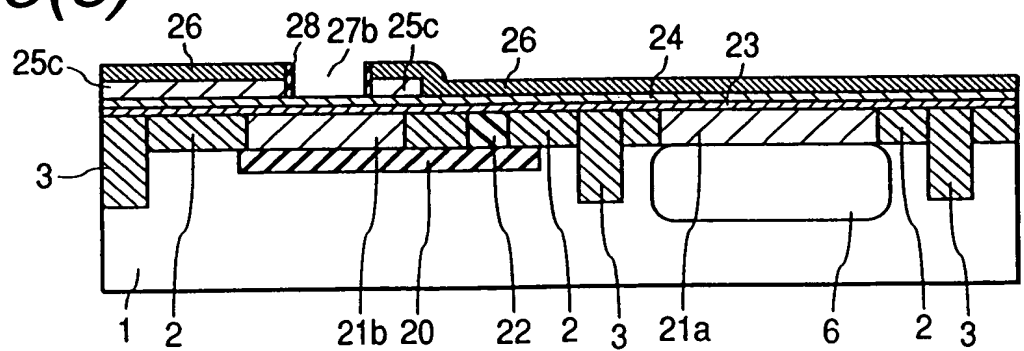
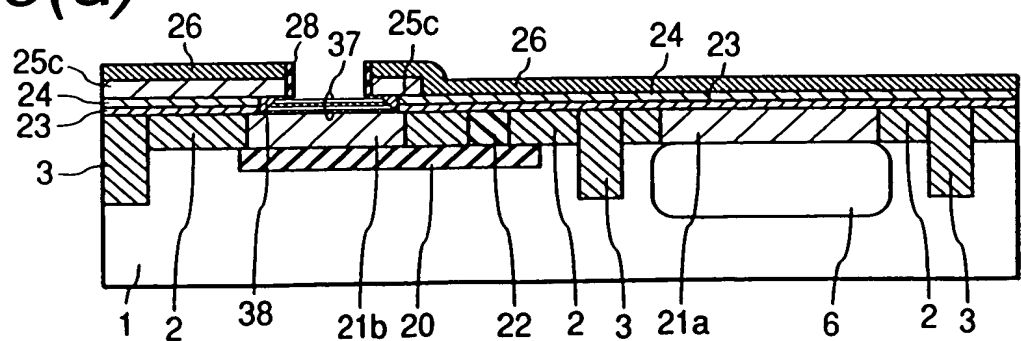
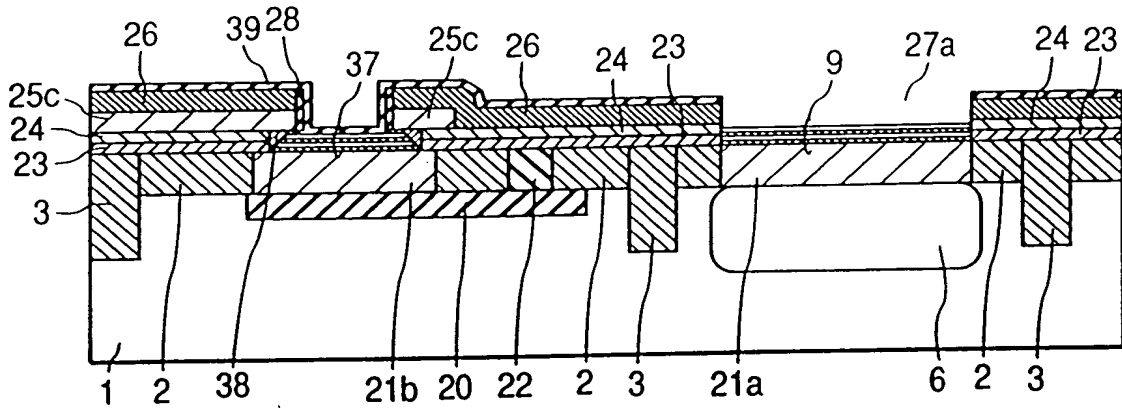


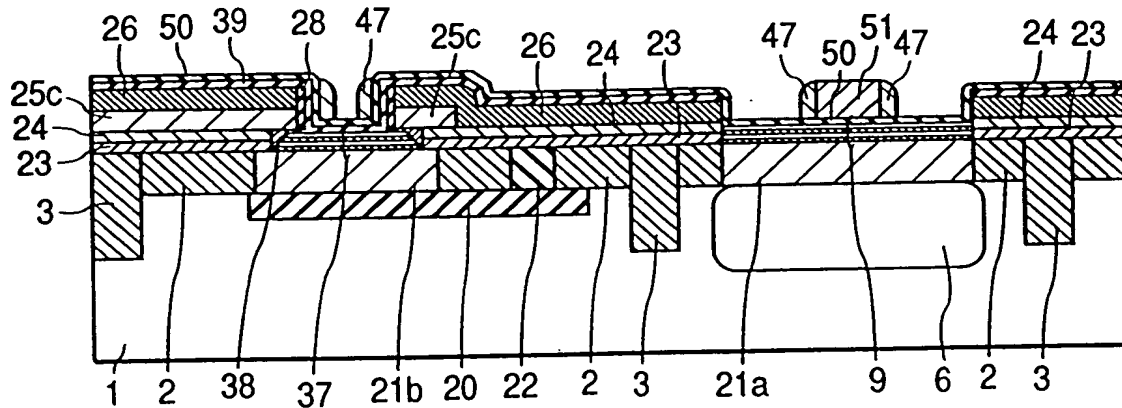
FIG. 29(d)



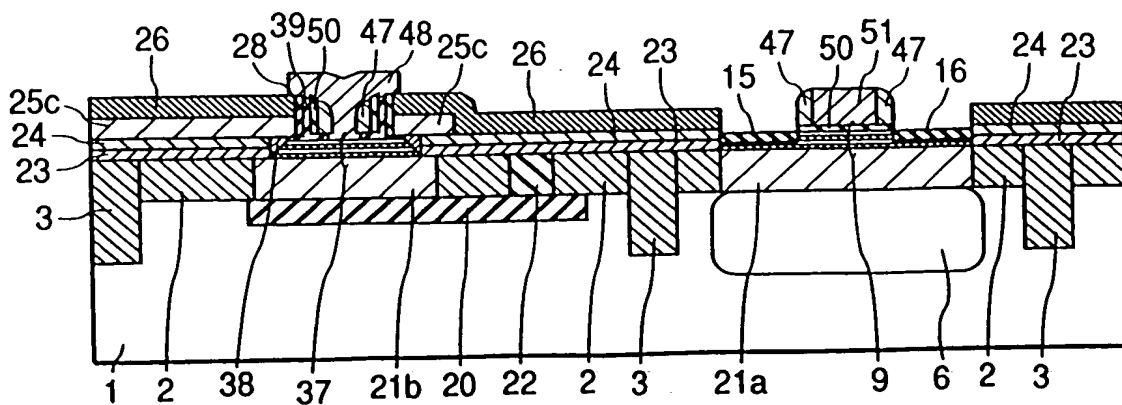
*FIG. 30(a)*



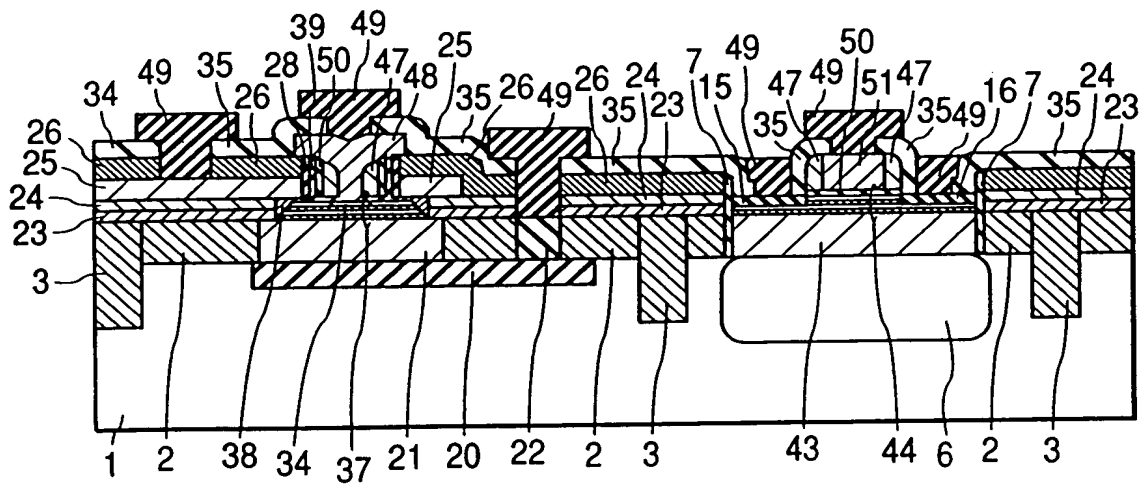
*FIG. 30(b)*



*FIG. 30(c)*

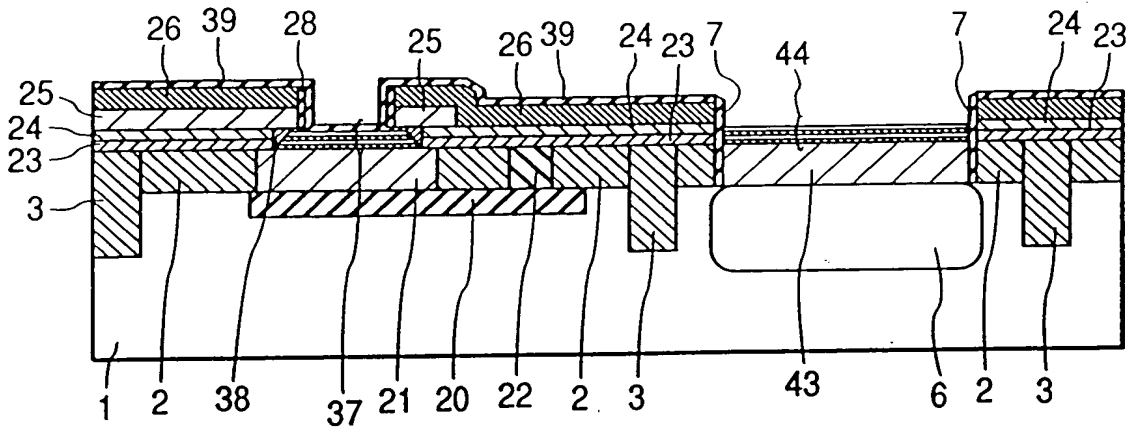


**FIG. 31**

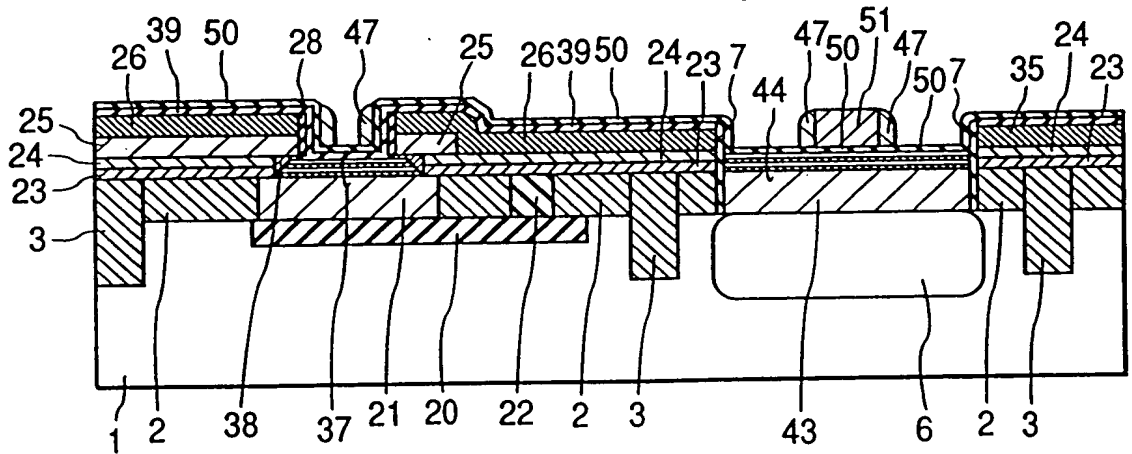


[illegible]

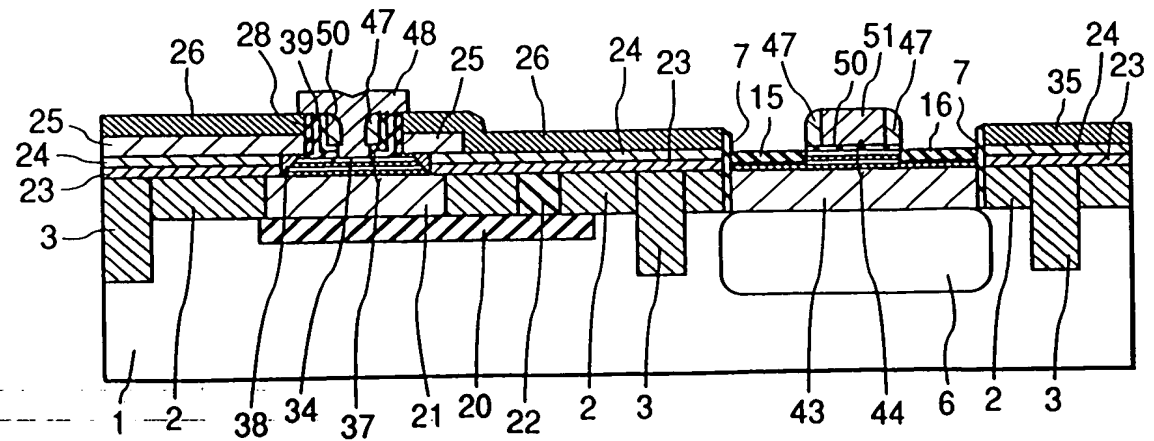
*FIG. 33(a)*



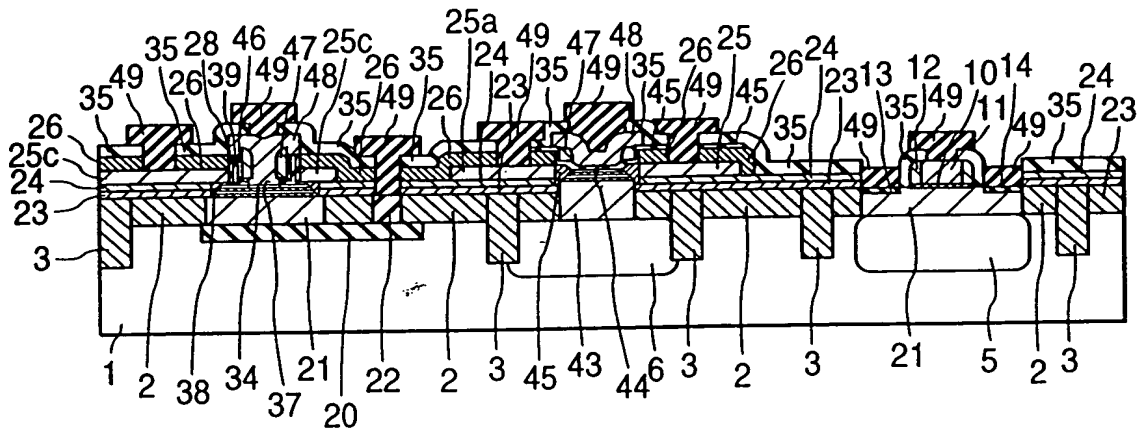
*FIG. 33(b)*



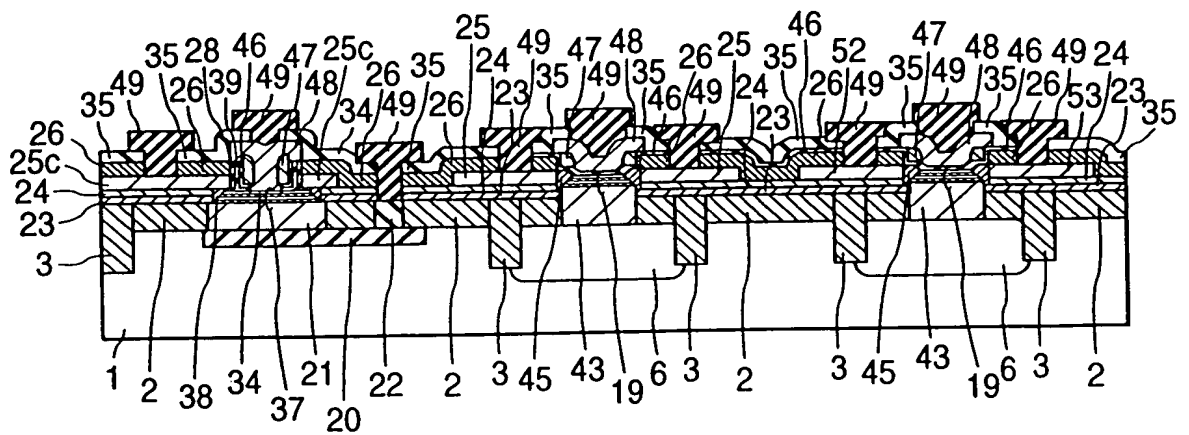
*FIG. 33(c)*



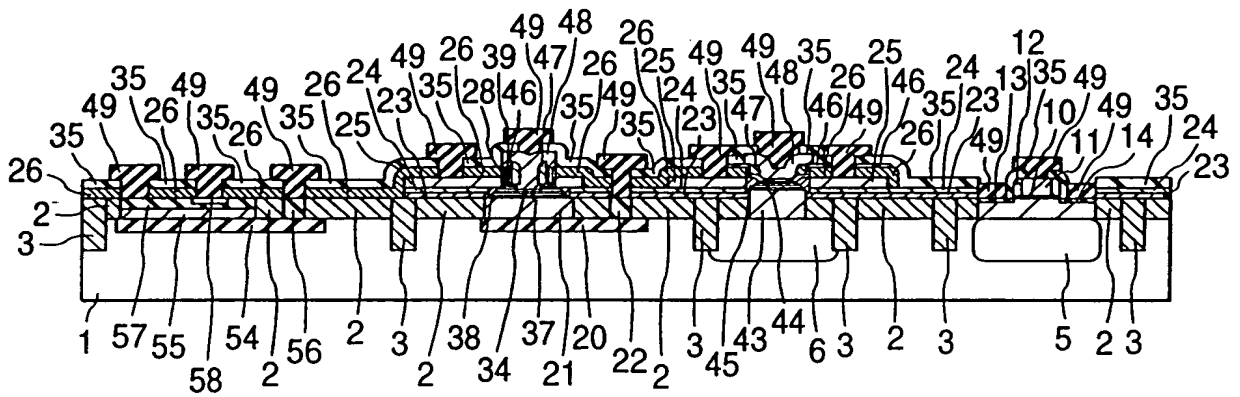
**FIG. 34**



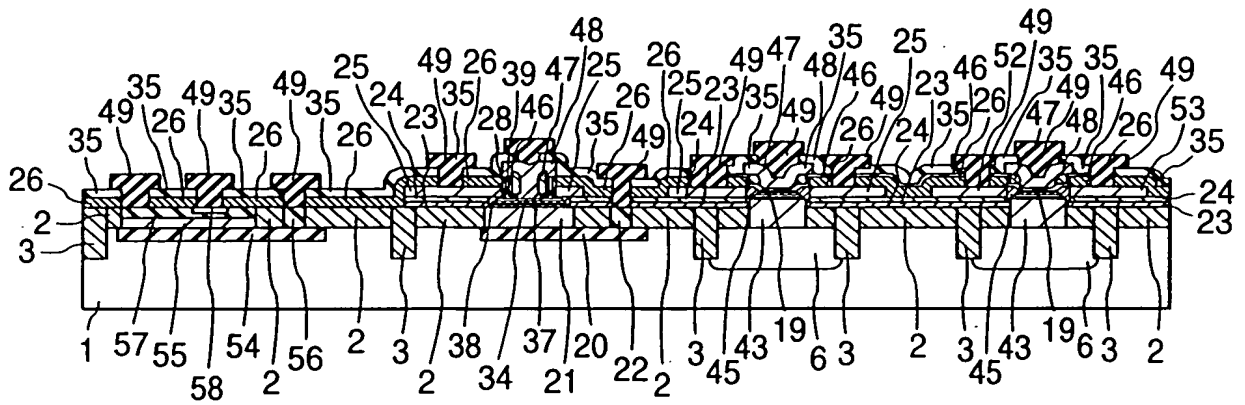
**FIG. 35**



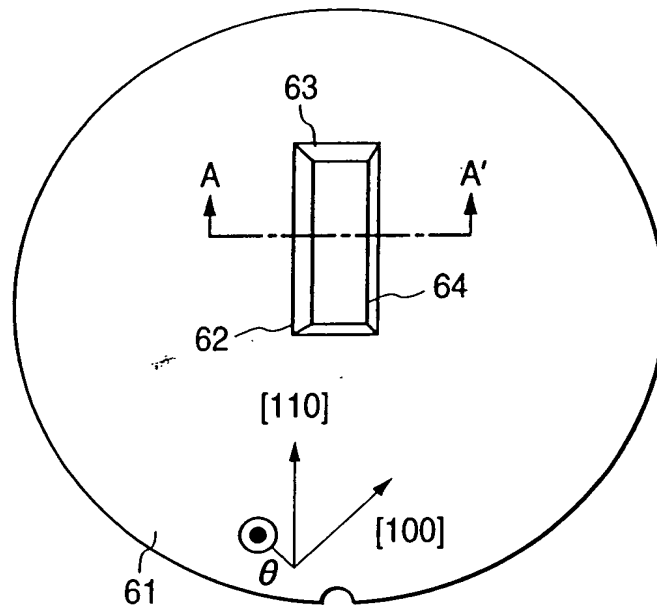
*FIG. 36*



*FIG. 37*



*FIG. 38(a)*



*FIG. 38(b)*

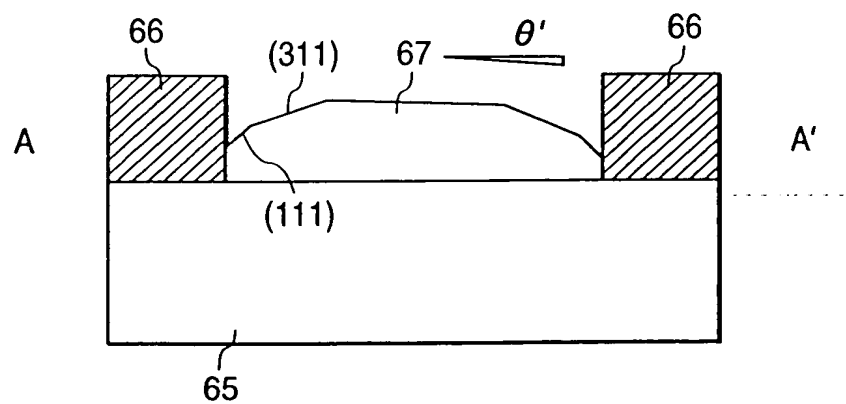


FIG. 39(a)

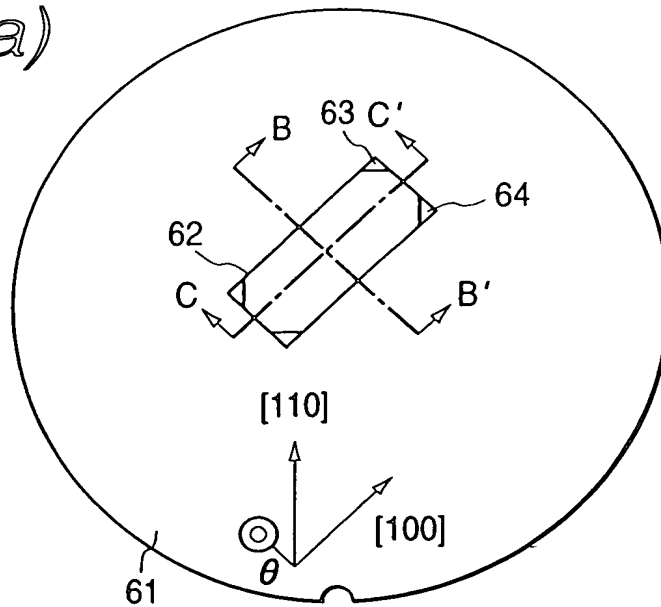


FIG. 39(b)

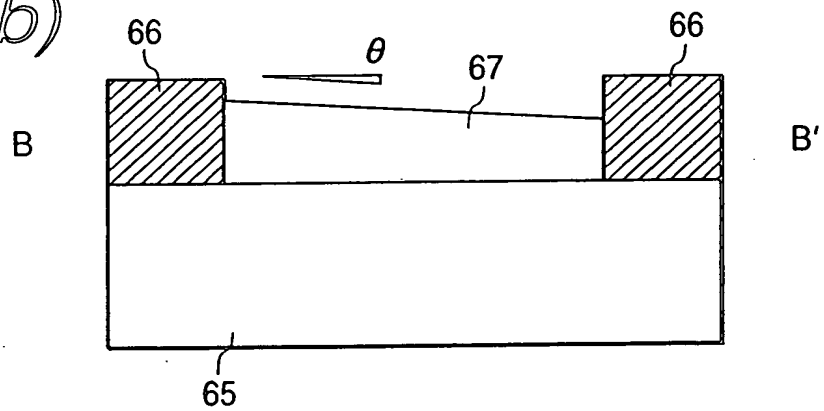


FIG. 39(c)

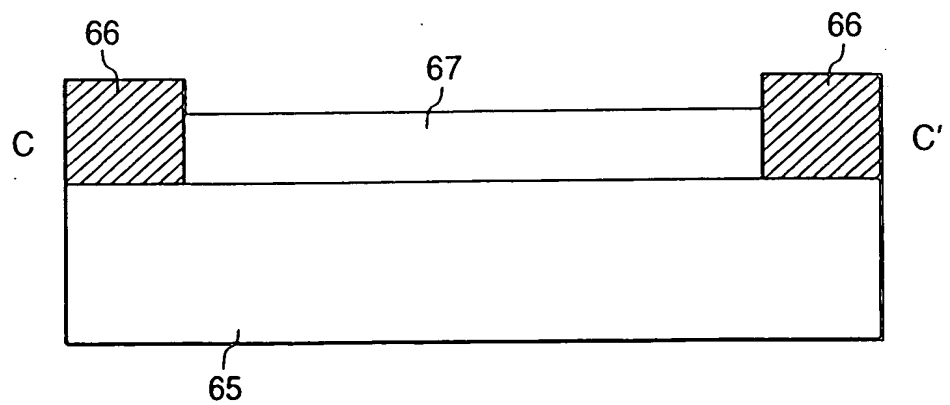


FIG. 40

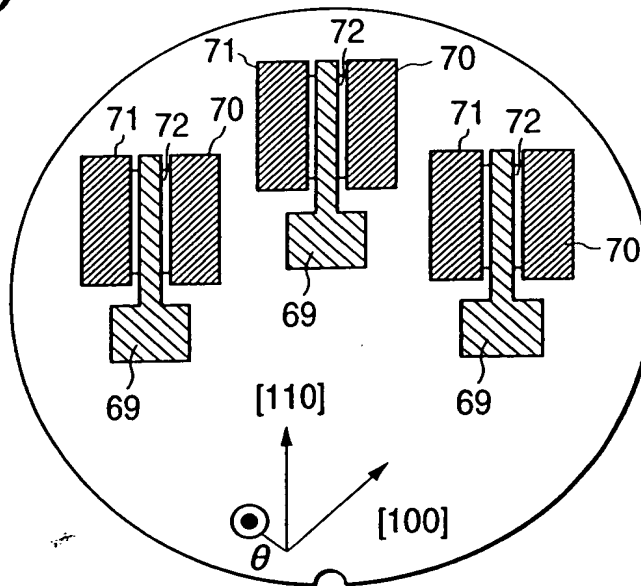
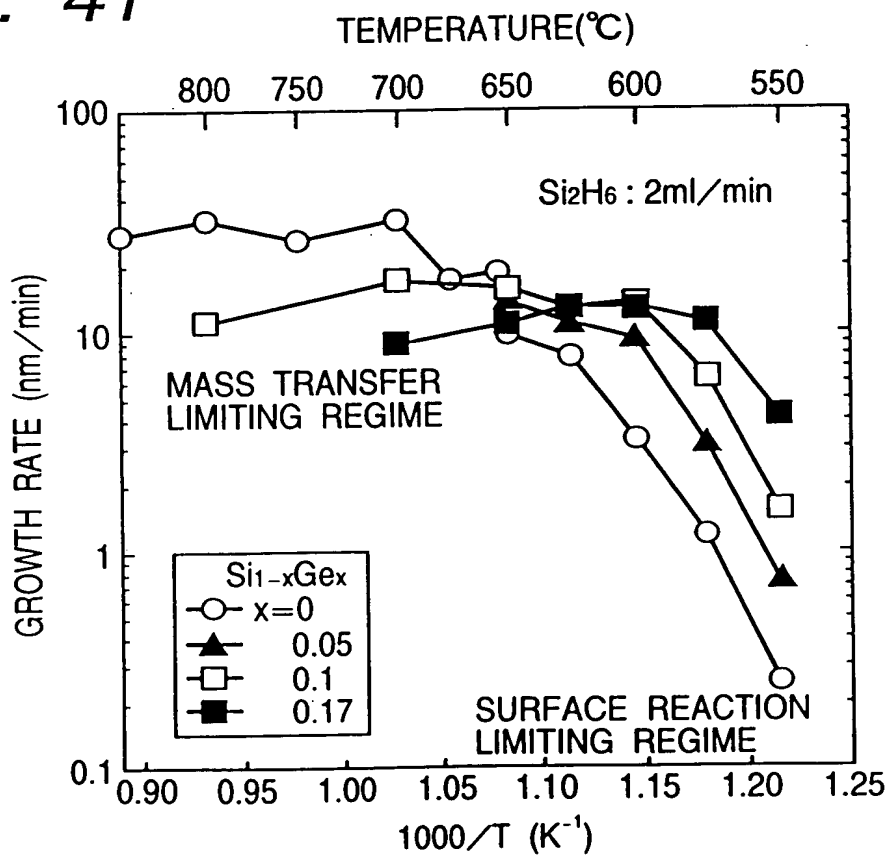
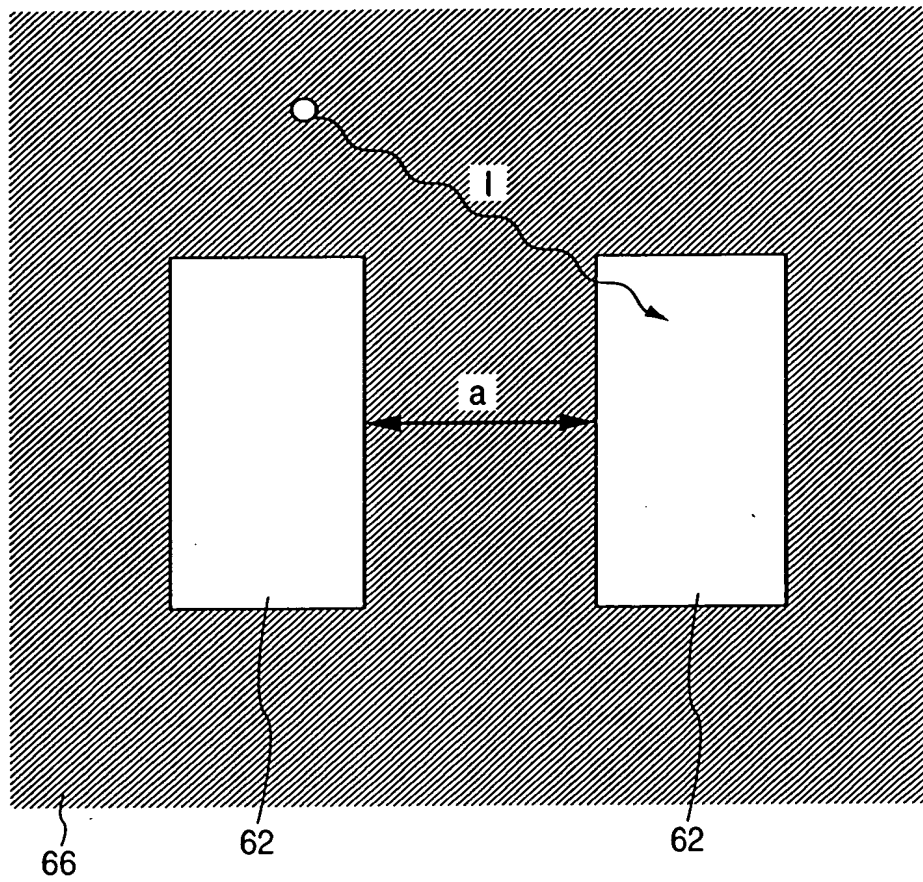


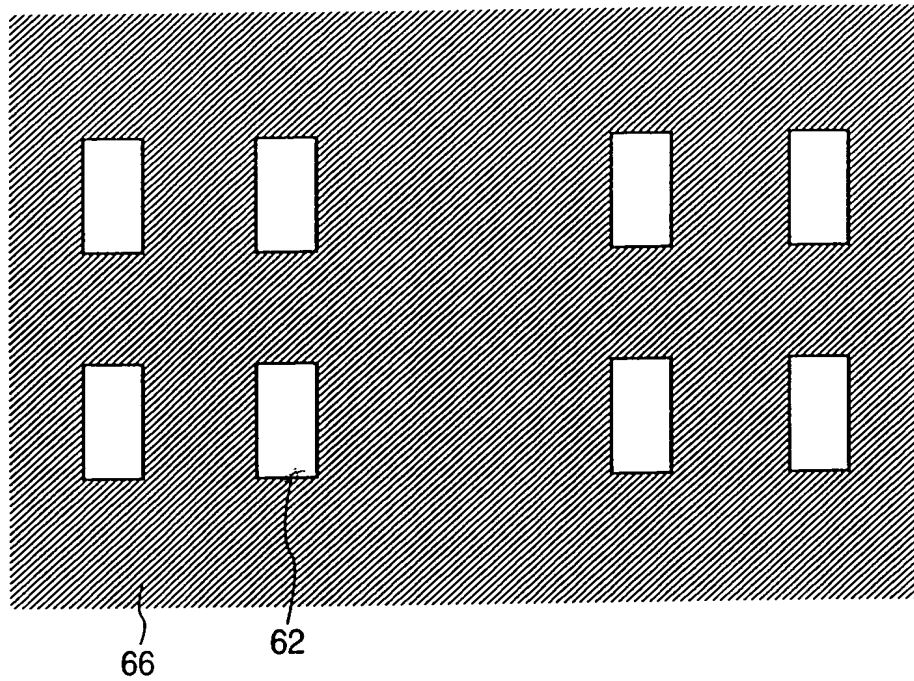
FIG. 41



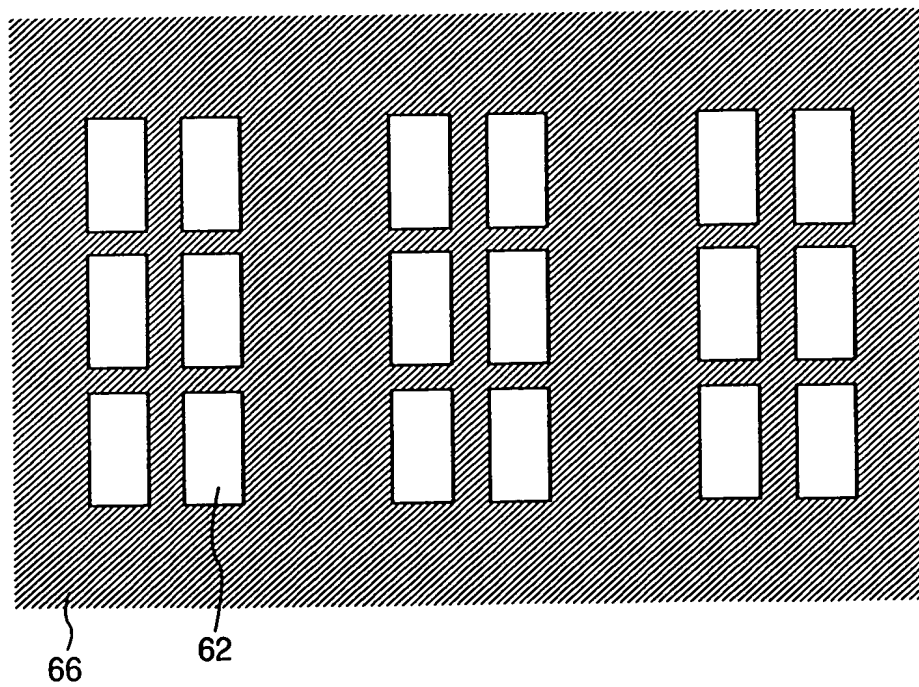
*FIG. 42*



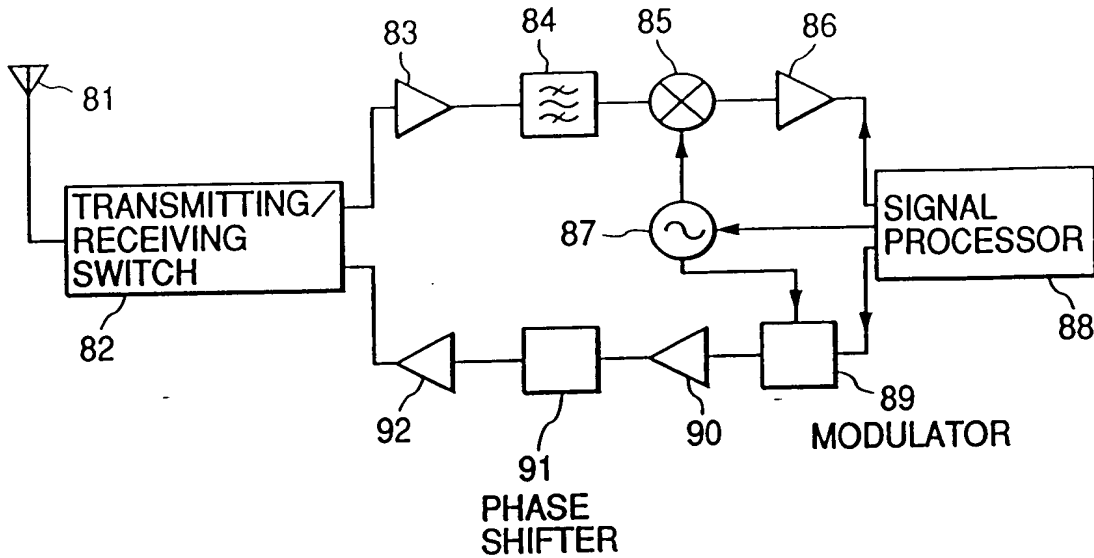
*FIG. 43(a)*



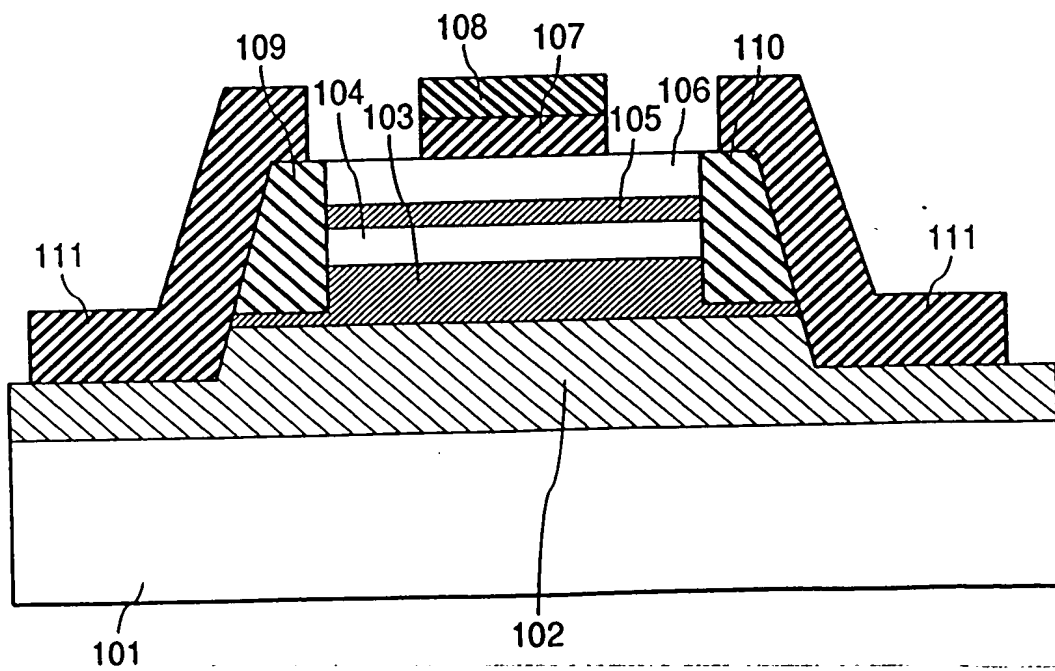
*FIG. 43(b)*



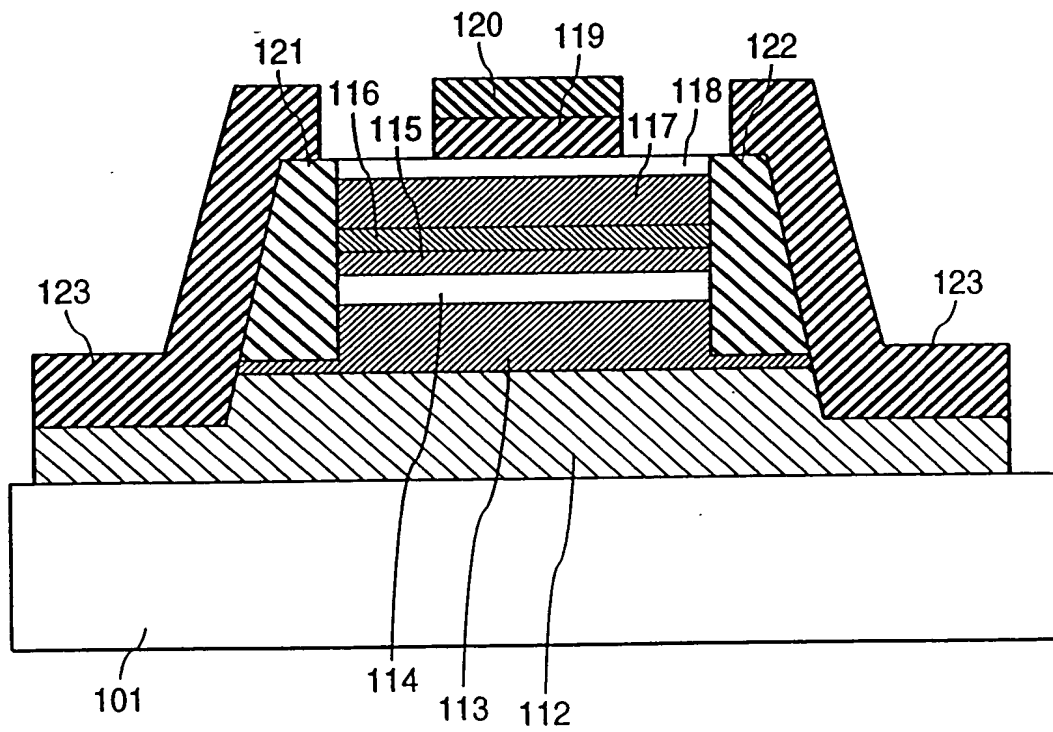
*FIG. 44*



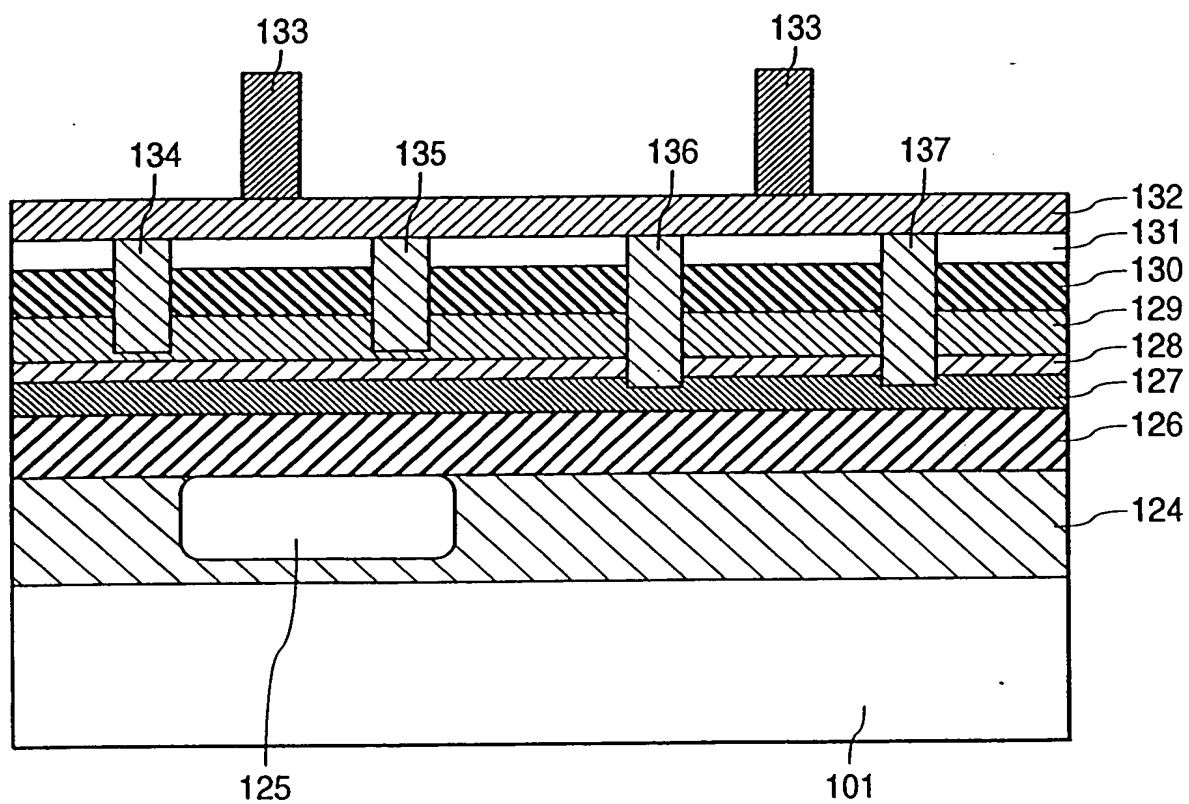
*FIG. 45 Prior Art*



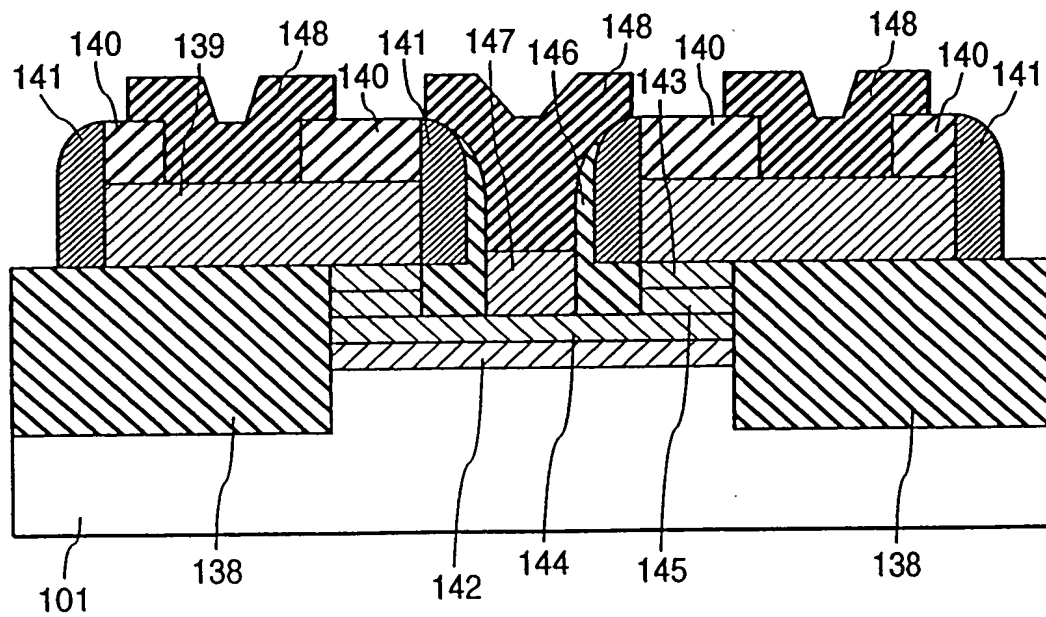
*FIG. 46 Prior Art*



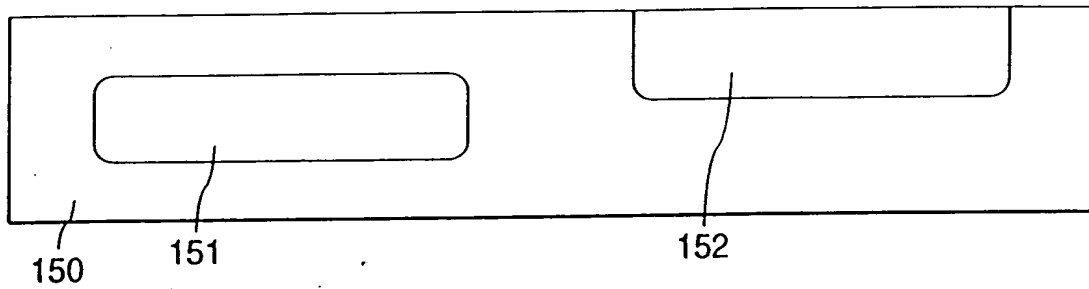
*FIG. 47 Prior Art*



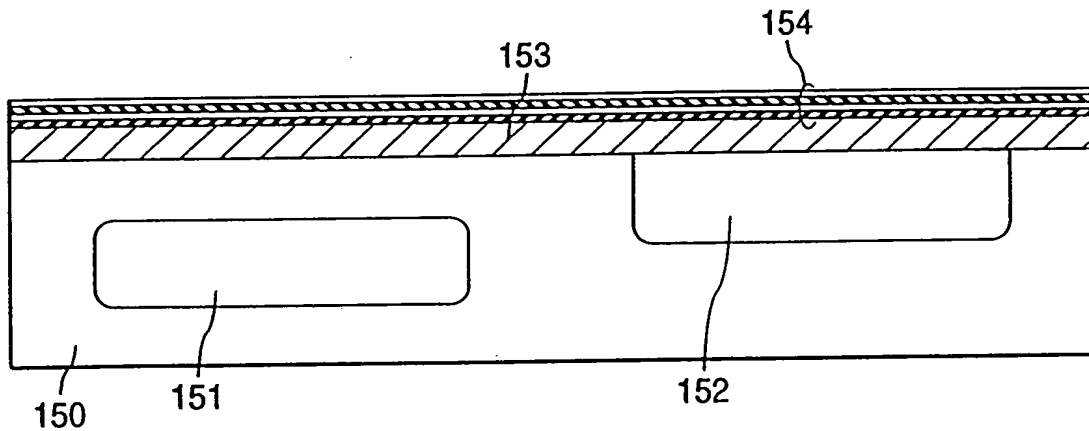
*FIG. 48 Prior Art*



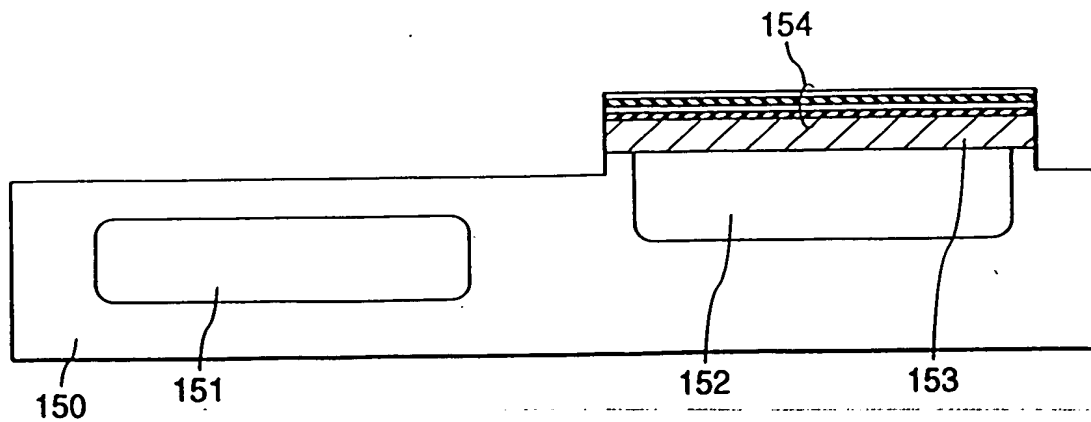
*FIG. 49(a) Prior Art*



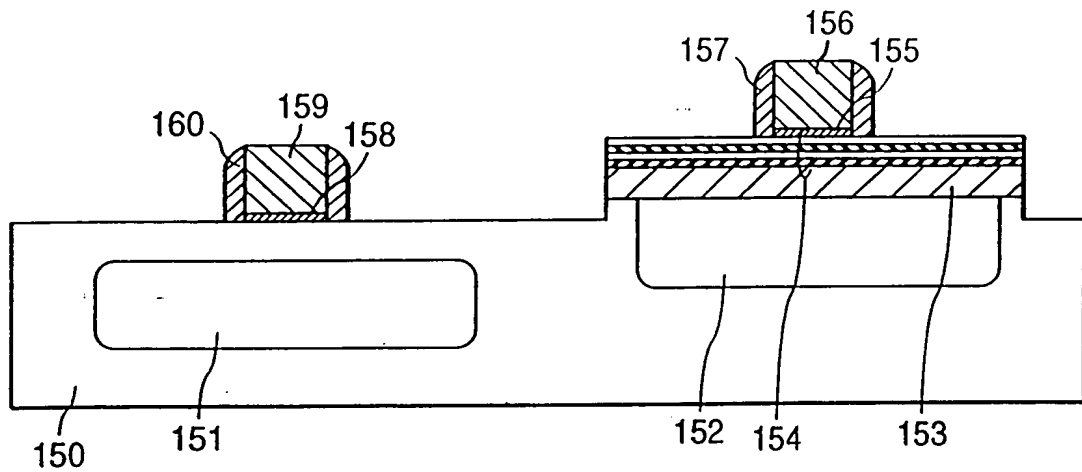
*FIG. 49(b) Prior Art*



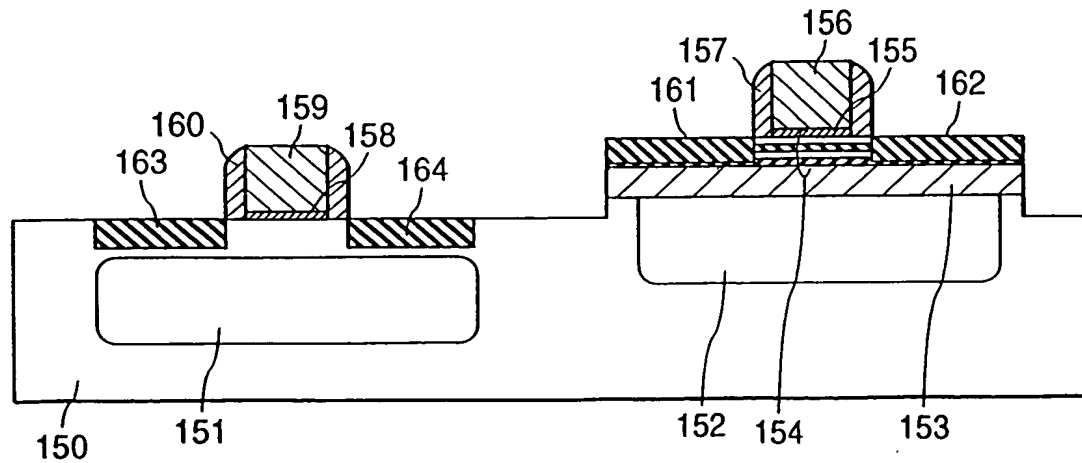
*FIG. 49(c) Prior Art*



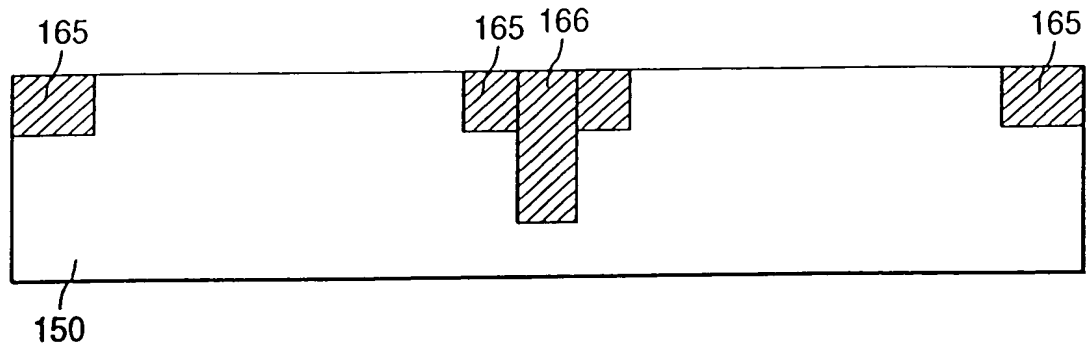
*FIG. 50(a) Prior Art*



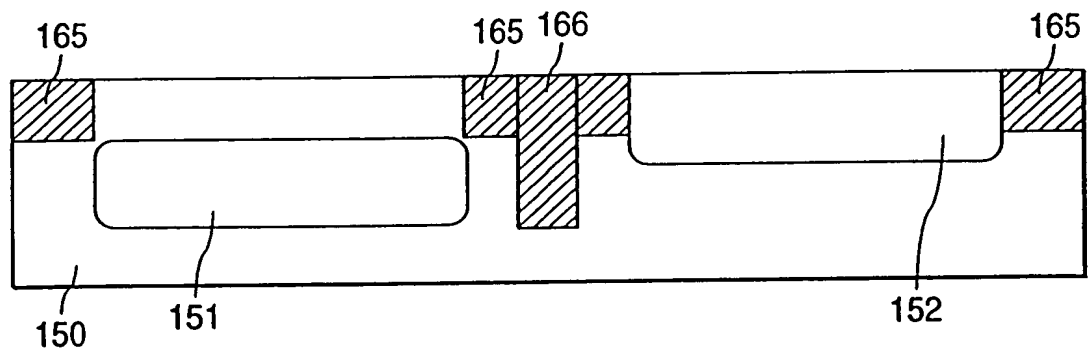
*FIG. 50(b) Prior Art*



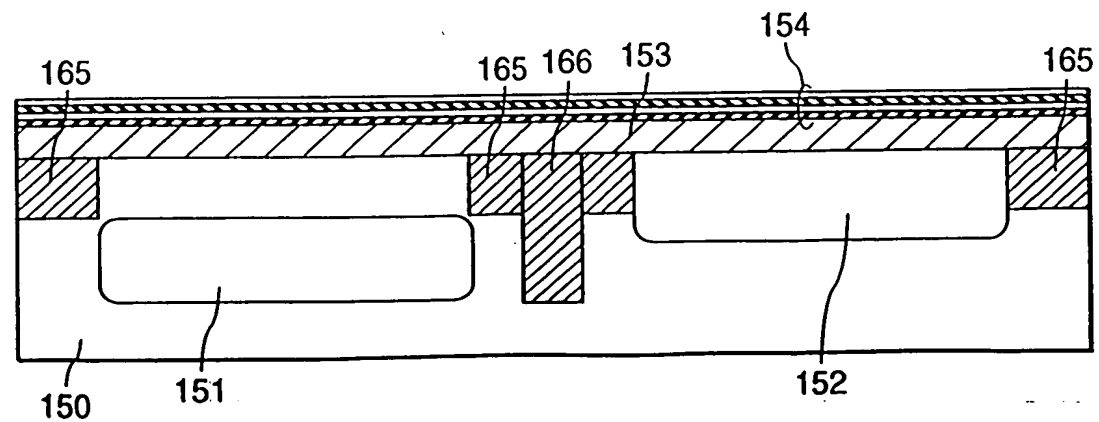
*FIG. 51(a) Prior Art*



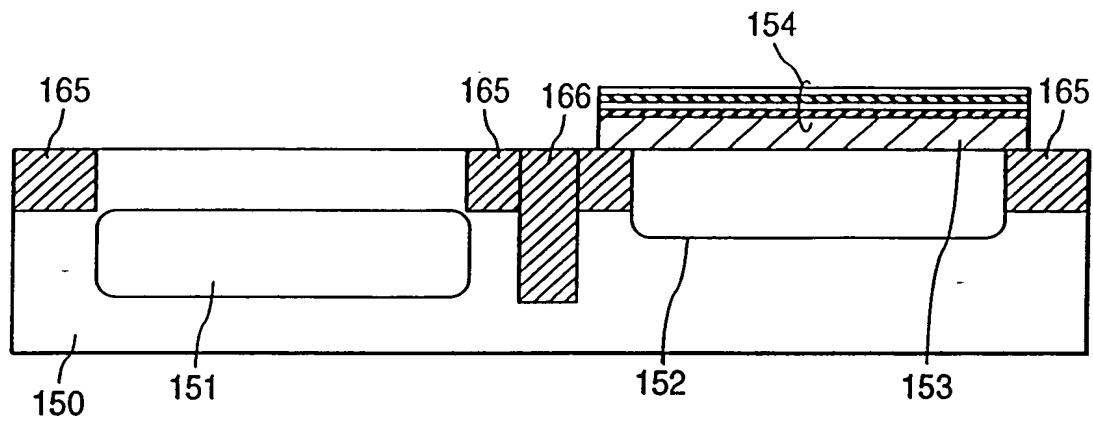
*FIG. 51(b) Prior Art*



*FIG. 51(c) Prior Art*



*FIG. 52(a) Prior Art*



*FIG. 52(b) Prior Art*

